EE 330
Lecture 39

Digital Circuits

Sizing of Devices for Logic Circuits (preliminary)
Ratio Logic
Other MOS Logic Families
Propagation Delay – basic characterization

EE 330
Lecture 40

Digital Circuits

- The Reference Inverter
- Propagation Delay – basic characterization
- Device Sizing (Inverter and multiple-input gates)

Due to unanticipated snow event when returning from Thanksgiving Break:

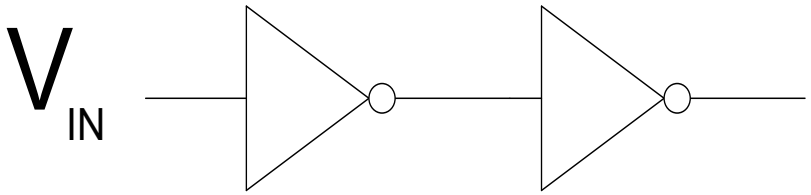
Please view the stream for Lecture 40 (from Fall 2024) prior to class on Friday which is reposted on the class WEB site. Lecture 41 will be given on Friday

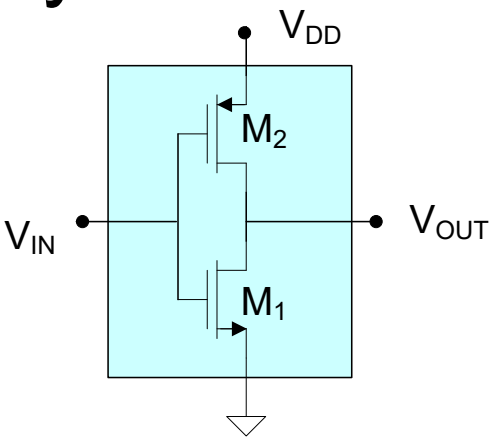
Fall 2025 Exam Schedule

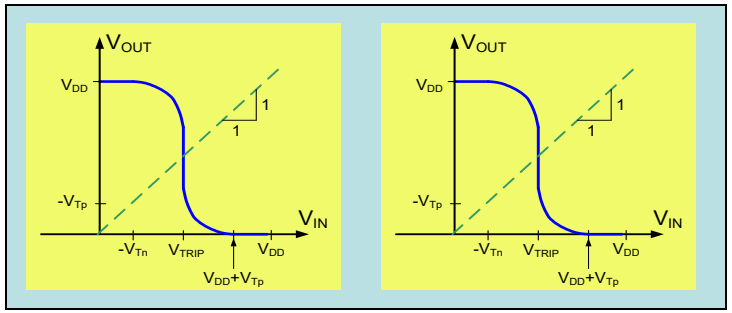
Exam 1	**Friday**	**Sept 26**
Exam 2	**Friday**	**October 24**
Exam 3	**Friday**	**Nov 21**
Final Exam	**Monday**	**Dec 15 12:00 - 2:00 PM**

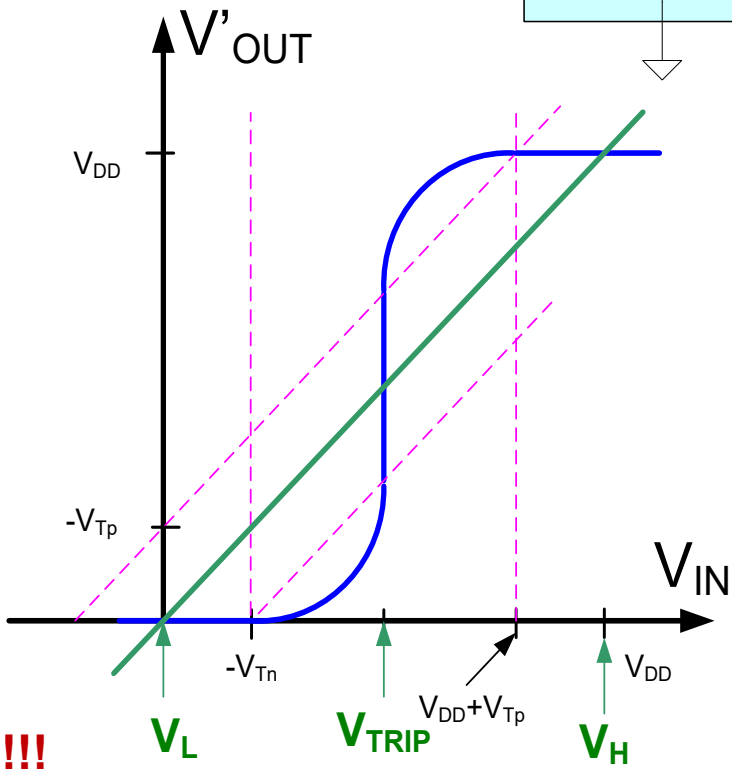
Review from last lecture

Inverter Transfer Characteristics of Inverter Pair for THIS Logic Family









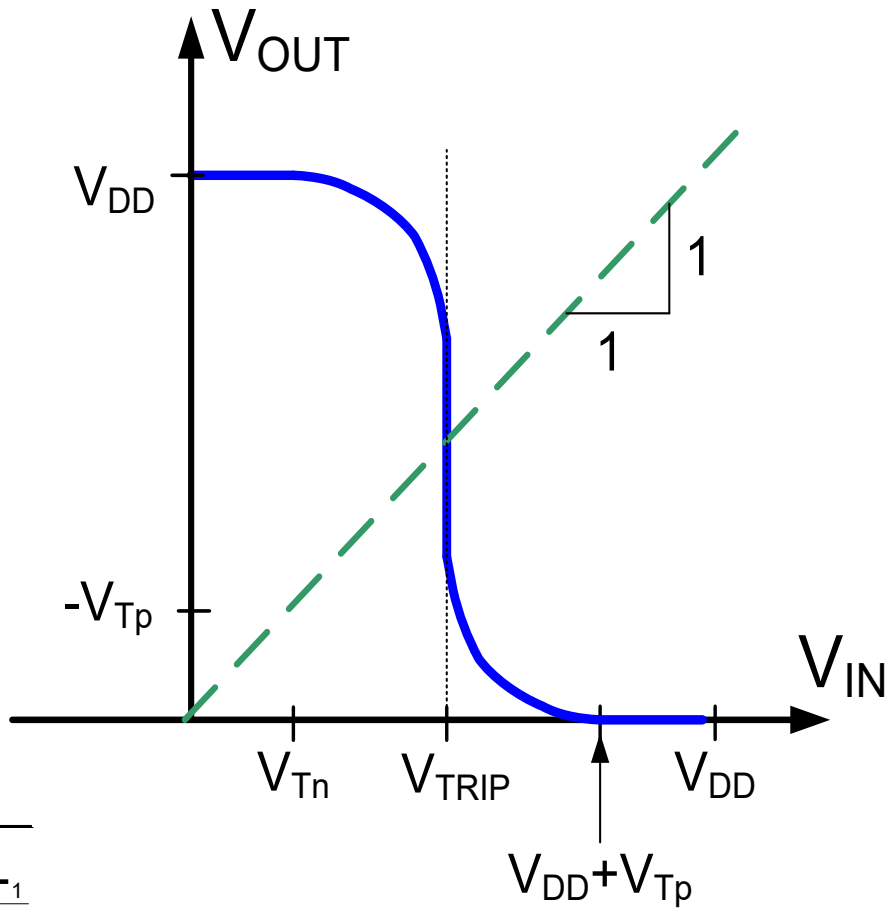
$V_H=V_{DD}$ and $V_L=0$

Note this is independent of device sizing for THIS logic family !!

Device sizing does not affect V_H and V_L !!!

Transfer characteristics of the static CMOS inverter

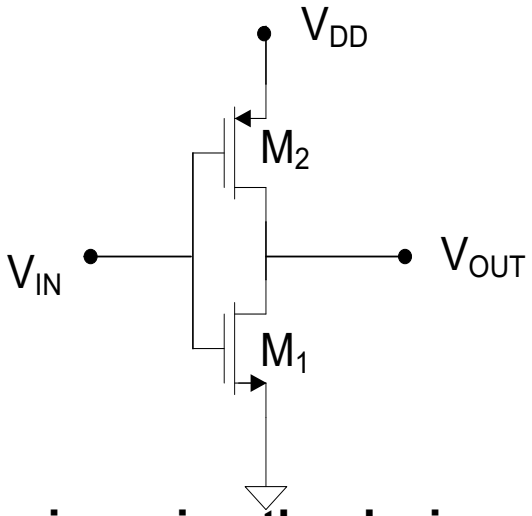
(Neglect λ effects)



From Case 3 analysis:

$$V_{IN} = \frac{\left(V_{Tn}\right) + \left(V_{DD} + V_{Tp}\right)\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}\frac{L_1}{L_2}}}{1 + \sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}\frac{L_1}{L_2}}}$$

Sizing of the Basic CMOS Inverter



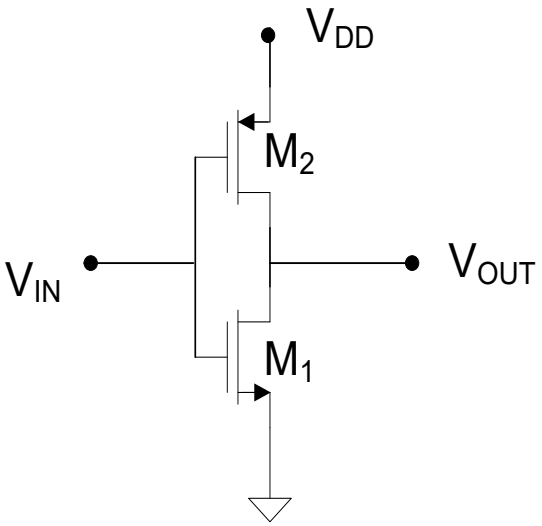
Most logic families require using the device sizing variables to determine acceptable V_H and V_L values

The characteristic that device sizes do not need to be used to establish V_H and V_L logic levels is a major advantage of this type of logic !!

How should M_1 and M_2 be sized?

How many degrees of freedom are there in the design of the inverter?

How should M_1 and M_2 be sized?



How many degrees of freedom are there in the design of the inverter?

$$\{ W_1, W_2, L_1, L_2 \}$$

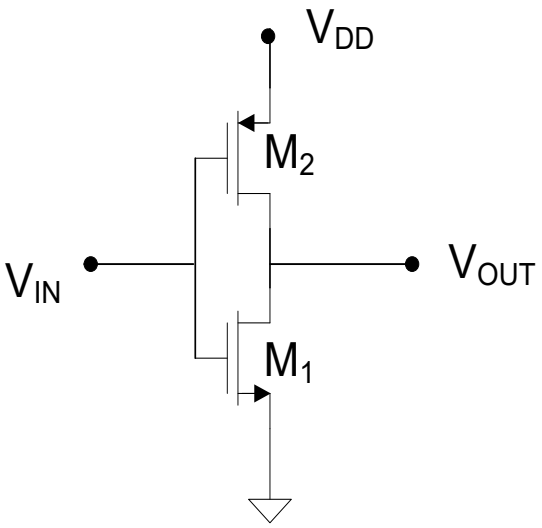
4 degrees of freedom

But in basic device model and in <u>most</u> performance metrics, W_1/L_1 and W_2/L_2 appear as ratios

effectively 2 degrees of freedom

$$\{ W_1/L_1, W_2/L_2 \}$$

How should M_1 and M_2 be sized?



$\{ W_1, W_2, L_1, L_2 \}$ **4 degrees of freedom** **Usually pick $L_1=L_2=L_{min}$**

That leaves **$\{ W_1, W_2 \}$** **effectively 2 degrees of freedom**

How are W_1 and W_2 chosen?

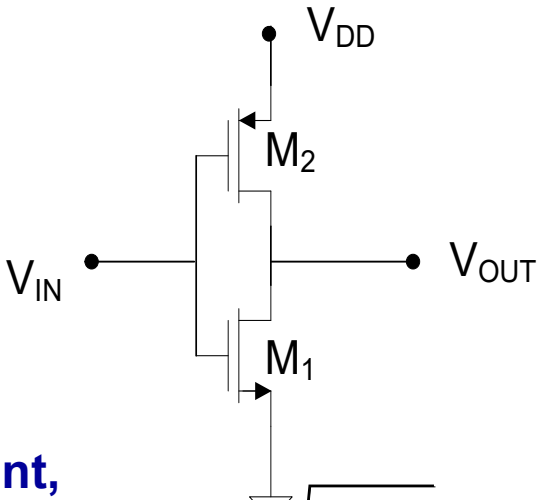
Depends upon what performance parameters are most important for a given application!

How should M_1 and M_2 be sized?

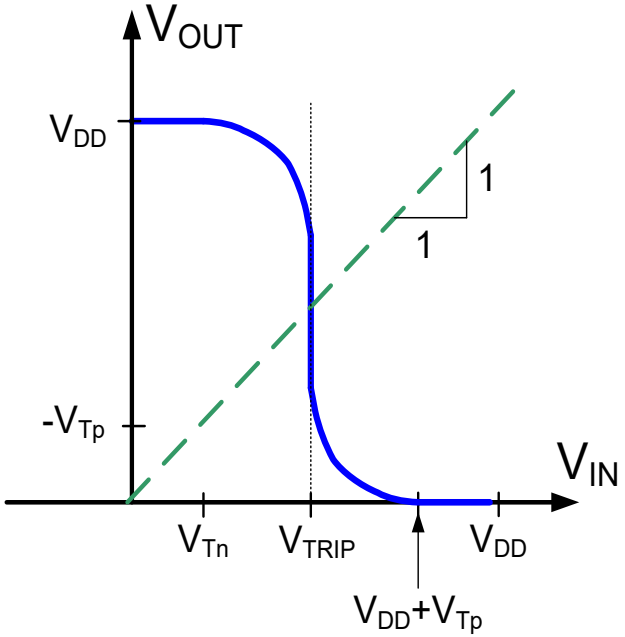
Pick $L_1=L_2=L_{min}$

<u>One</u> popular sizing strategy:

1. **Pick $W_1=W_{MIN}$ to minimize area of M_1**
2. **Pick W_2 to set trip-point at $V_{DD}/2$**



Observe Case 3 provides expression for V_{TRIP}



Thus, at the trip point,

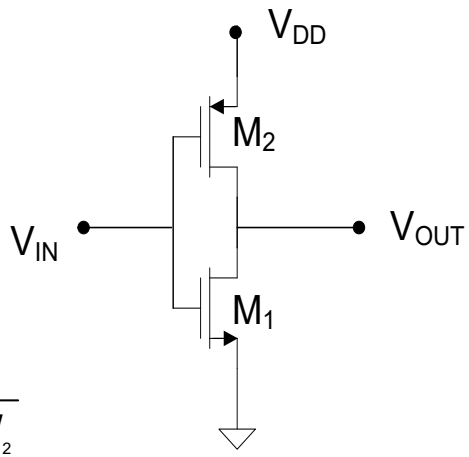
$$V_{OUT}=V_{IN}=V_{TRIP}=\frac{(V_{Tn})+(V_{DD}+V_{Tp})\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}}}{1+\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}}}$$

If $V_{Tn}=-V_{Tp}$

$$\frac{V_{DD}}{2}=\frac{(V_{Tn})+(V_{DD}-V_{Tn})\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}}}{1+\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}}}$$

How should M_1 and M_2 be sized?

Pick $L_1=L_2=L_{min}$

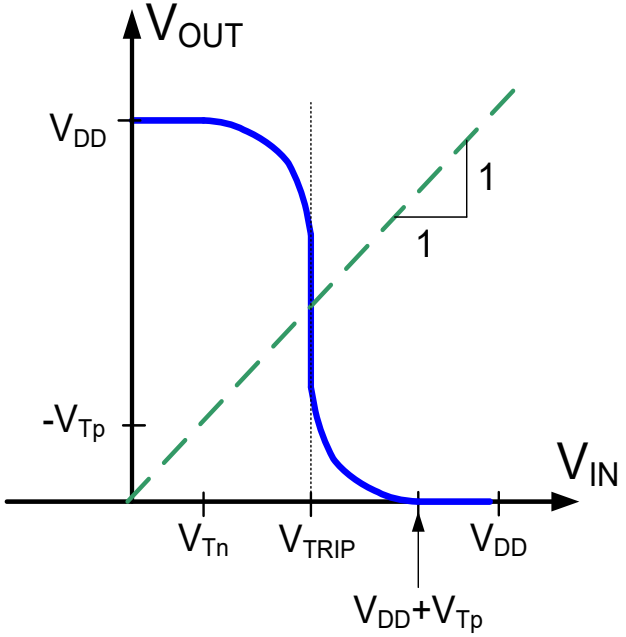


<u>One</u> popular sizing strategy:

1. **Pick $W_1=W_{MIN}$ to minimize area of M_1**
2. **Pick W_2 to set trip-point at $V_{DD}/2$**

Observe Case 3 provides expression for V_{TRIP}

(solution continued)



$$\frac{V_{DD}}{2}=\frac{(V_{Tn})+(V_{DD}-V_{Tn})\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}}}{1+\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}}}$$

solving for $\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}}$ **we obtain**

$$\sqrt{\frac{\mu_p}{\mu_n}\frac{W_2}{W_1}}=\frac{V_{Tn}-\frac{V_{DD}}{2}}{-\frac{V_{DD}}{2}+V_{Tn}}=1$$

This is independent of V_{Tn} and V_{DD}!

thus

$$\frac{W_2}{W_1}=\frac{\mu_n}{\mu_p} \Rightarrow W_2=\frac{\mu_n}{\mu_p}W_{MIN}\simeq 3W_{MIN}$$

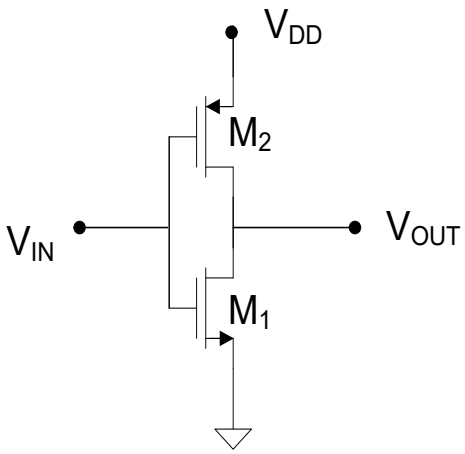
How should M_1 and M_2 be sized?

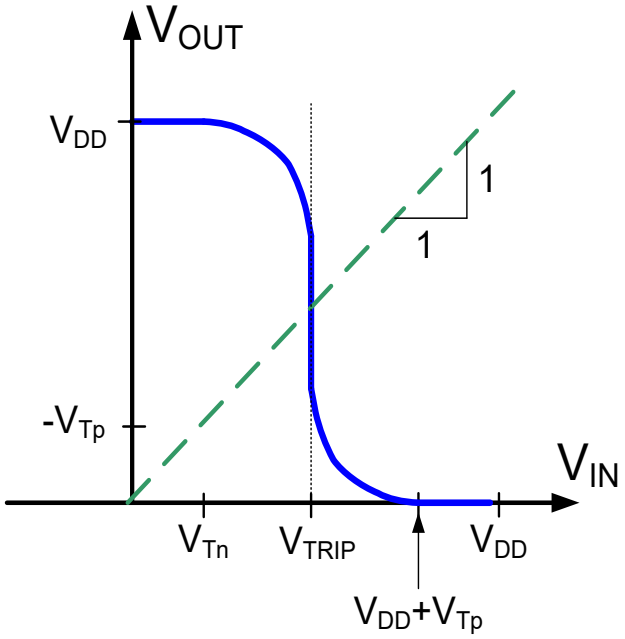
Pick $L_1=L_2=L_{min}$

<u>One</u> popular sizing strategy:

1. **Pick $W_1=W_{MIN}$ to minimize area of M_1**
2. **Pick W_2 to set trip-point at $V_{DD}/2$**

Observe Case 3 provides expression for V_{TRIP}





Summary: $V_{TRIP} = \frac{V_{DD}}{2}$ **sizing strategy**

$L_1=L_2=L_{min}$

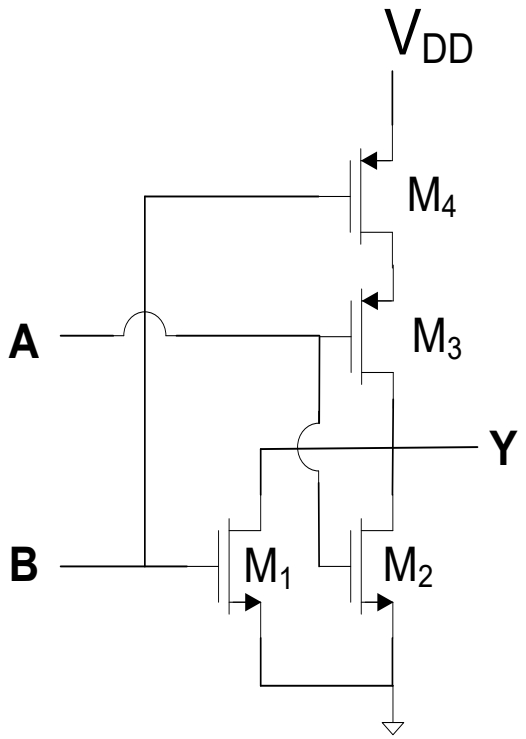
$W_1=W_{MIN}$

$$W_2 = \frac{\mu_n}{\mu_p} W_{MIN} \simeq 3W_{MIN}$$

(dependent upon assumption $V_{Tp}= -V_{Tn}$)

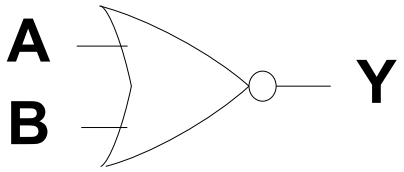
Other sizing strategies will be discussed later !

Extension of Basic CMOS Inverter to Multiple-Input Gates



A	B	Y
0	0	1
0	1	0
1	0	0
1	1	0

Truth Table



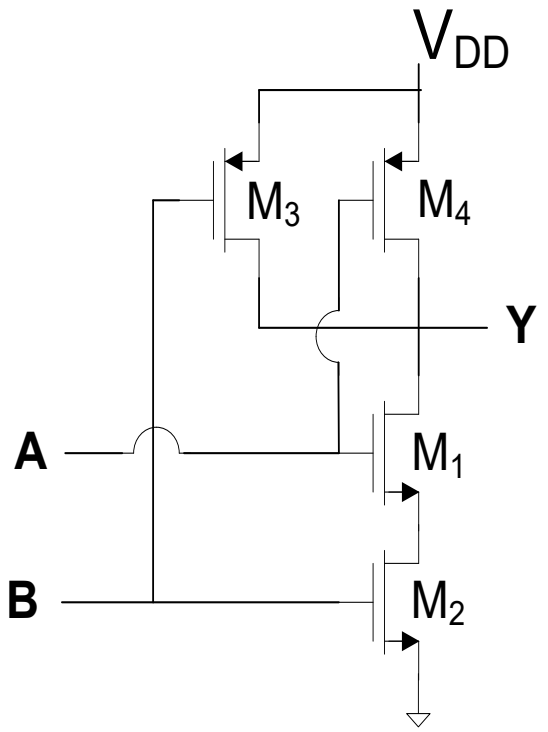
Performs as a 2-input NOR Gate

Can be easily extended to an n-input NOR Gate

$V_H=V_{DD}$ and $V_L=0$ (inherited from inverter analysis)

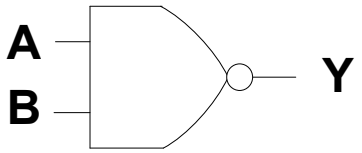
analysis not shown here but straightforward and consistent with claim that performance of gates in logic family determined by those of basic inverter

Extension of Basic CMOS Inverter to Multiple-Input Gates



A	B	Y
0	0	1
0	1	1
1	0	1
1	1	0

Truth Table

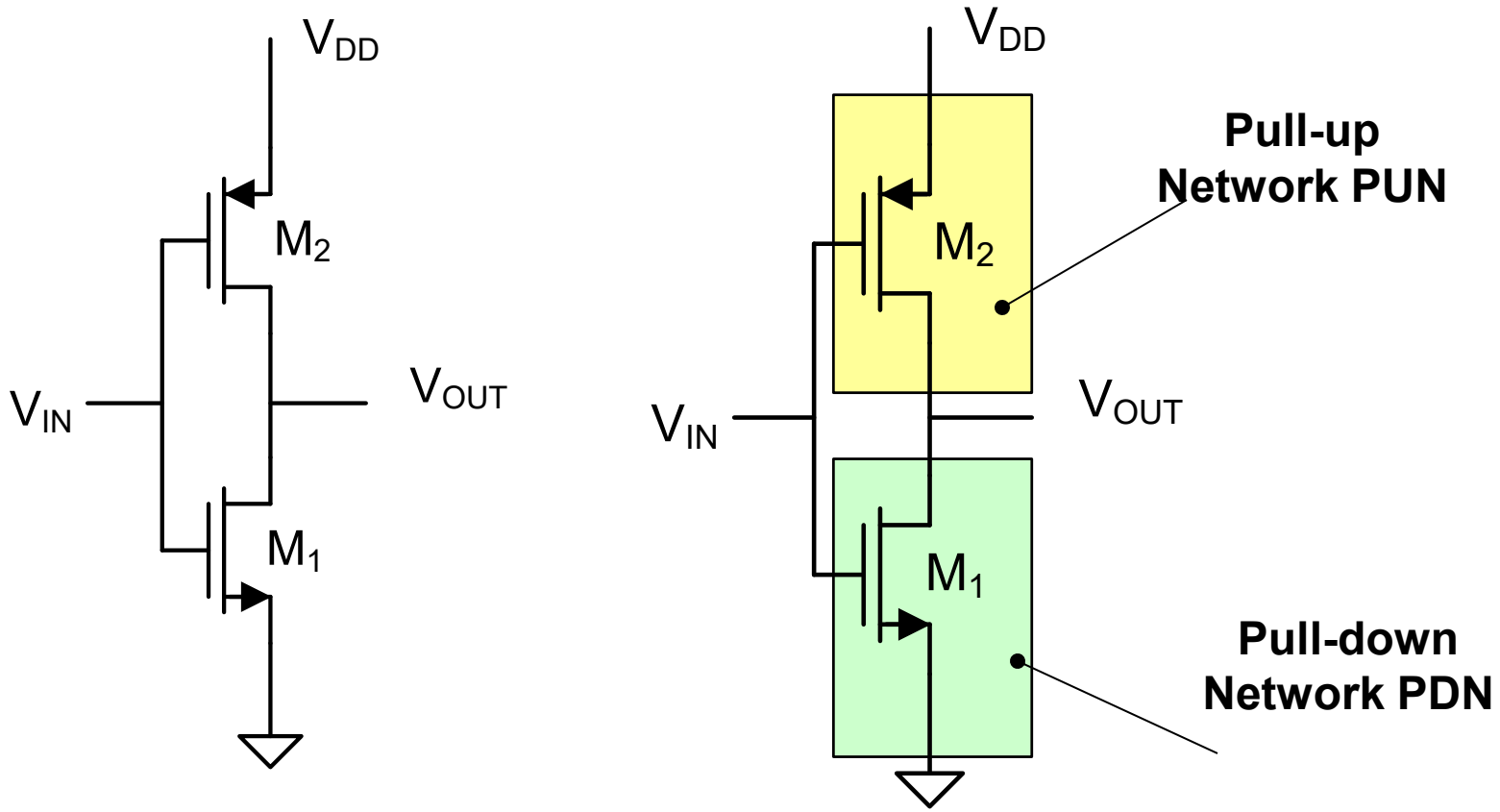


Performs as a 2-input NAND Gate

Can be easily extended to an n-input NAND Gate

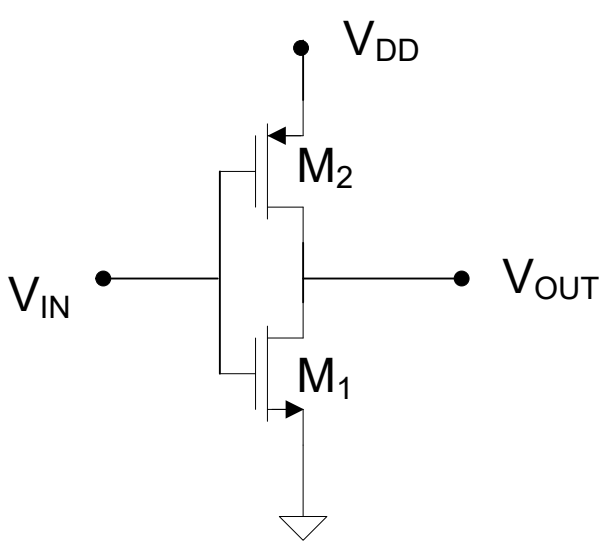
$V_H=V_{DD}$ and $V_L=0$ (inherited from inverter analysis)

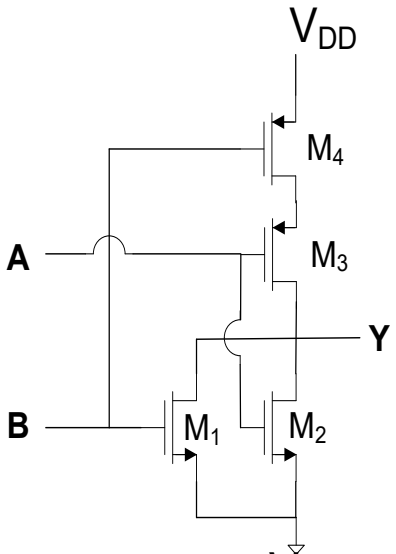
Static CMOS Logic Family

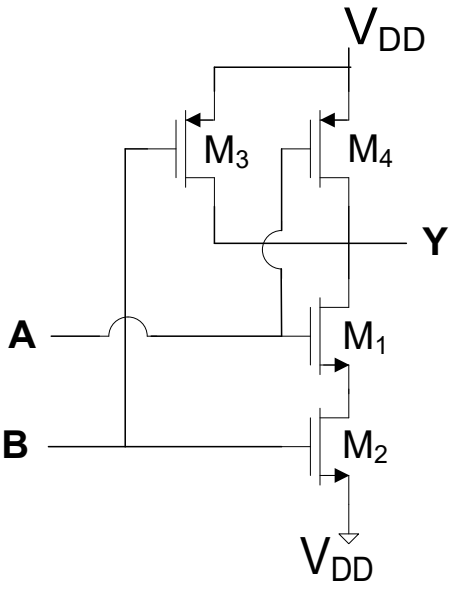


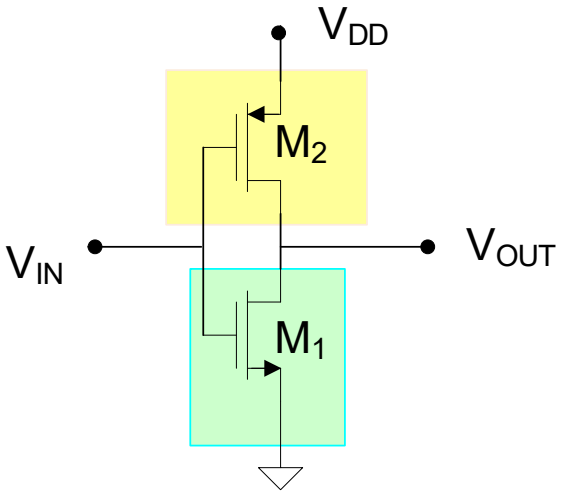
- **Observe PUN is p-channel, PDN is n-channel**
- **Claim: If PUN comprised of p-channel, PDN comprised of n-channels and one and only one is conducting , then $V_H=V_{DD}$ and $V_L=0$**
- **inherited from inverter analysis**

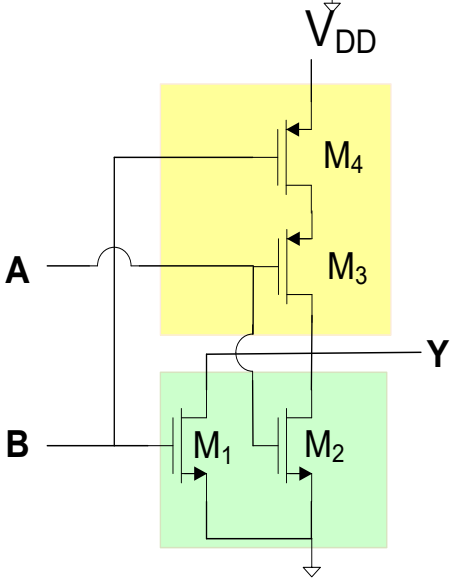
Static CMOS Logic Family

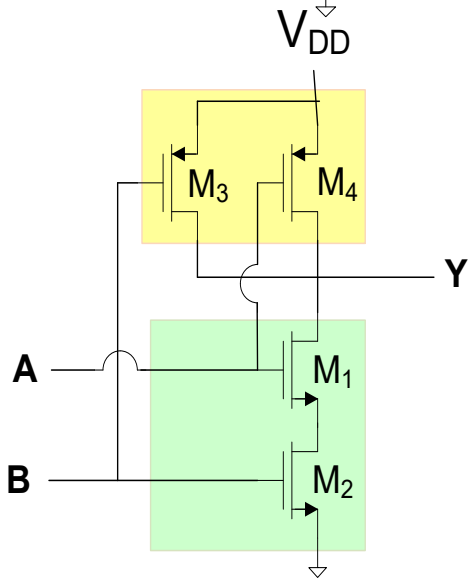












n-channel PDN and p-channel PUN

$V_H=V_{DD}$, $V_L=0V$ (same as for inverter!)

Digital Circuit Design

- Hierarchical Design
- Basic Logic Gates
- Properties of Logic Families
- Characterization of CMOS Inverter
- Static CMOS Logic Gates
  - Ratio Logic
- Propagation Delay
  - Simple analytical models
    - FI/OD
    - Logical Effort
  - Elmore Delay
- Sizing of Gates
  - The Reference Inverter
- Propagation Delay with Multiple Levels of Logic
- Optimal driving of Large Capacitive Loads
- Power Dissipation in Logic Circuits
- Other Logic Styles
- Array Logic
- Ring Oscillators

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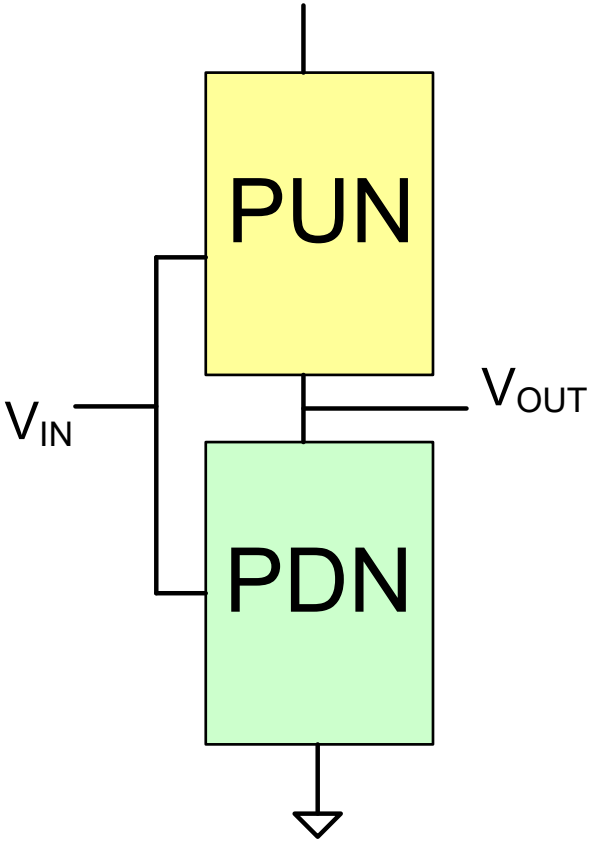
done

partial

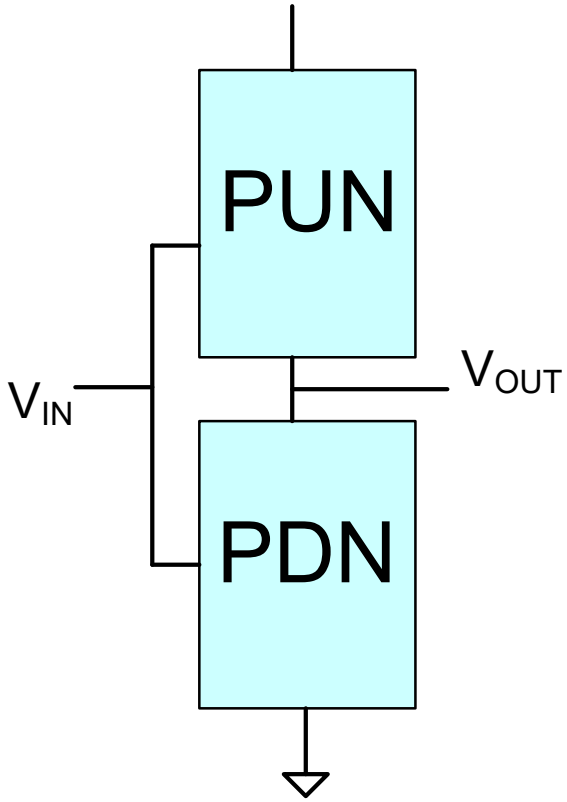
General Logic Family



Compound Gate in CMOS Process

p-channel PUN
n-channel PDN

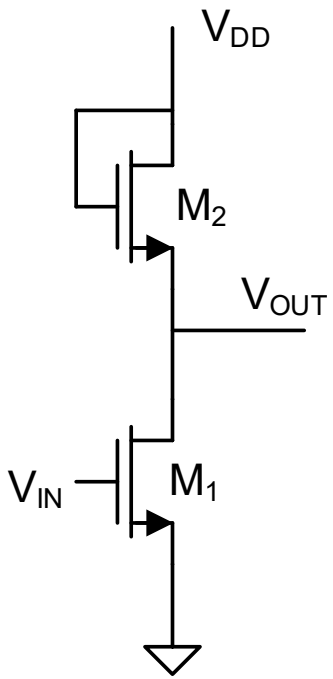
$V_H=V_{DD}$, $V_L=0V$ (same as for inverter!)



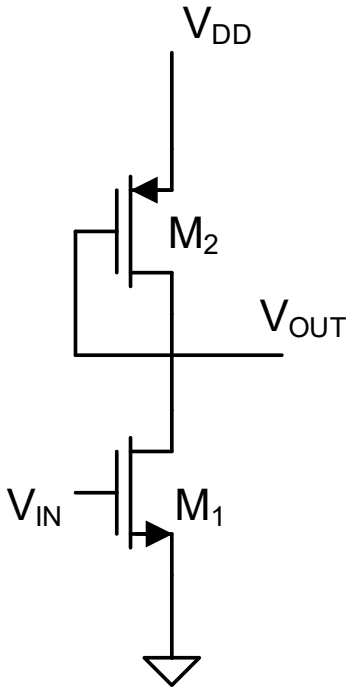
Arbitrary PUN and PDN

Other MOS Logic Families

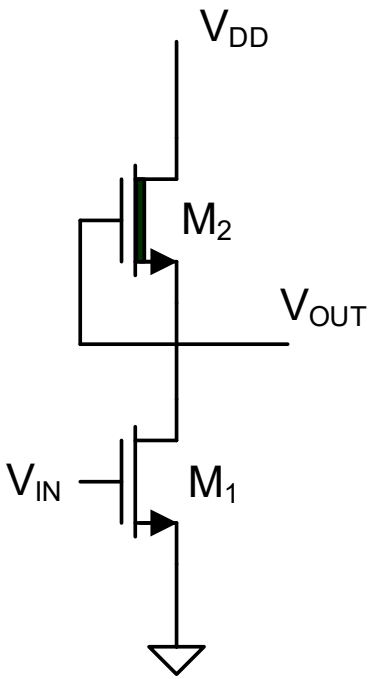
(Arbitrary PUN and PDN)



Enhancement Load
NMOS



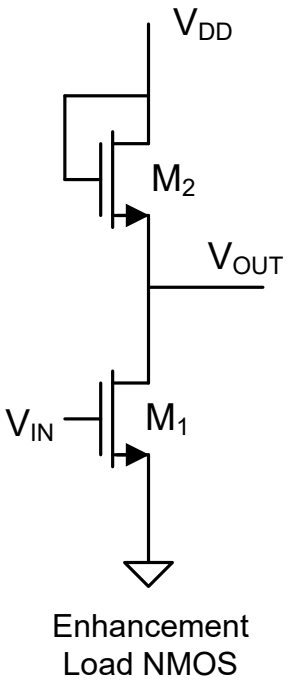
Enhancement Load
Pseudo-NMOS



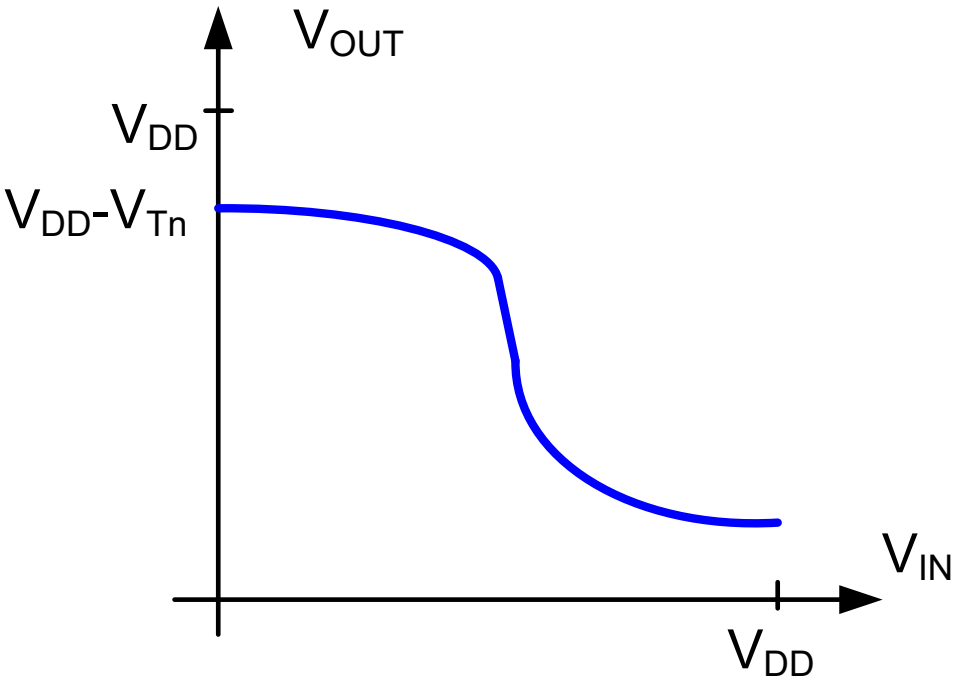
Depletion Load
NMOS

These are termed “ratio logic” gates

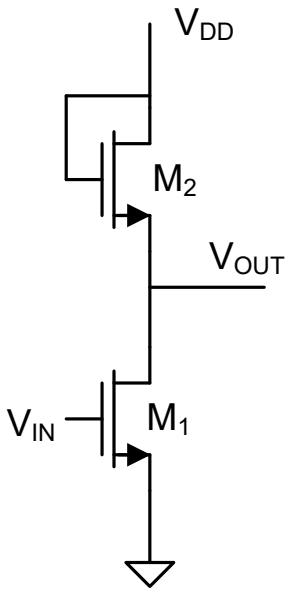
Other CMOS/MOS Logic Families



Enhancement
Load NMOS

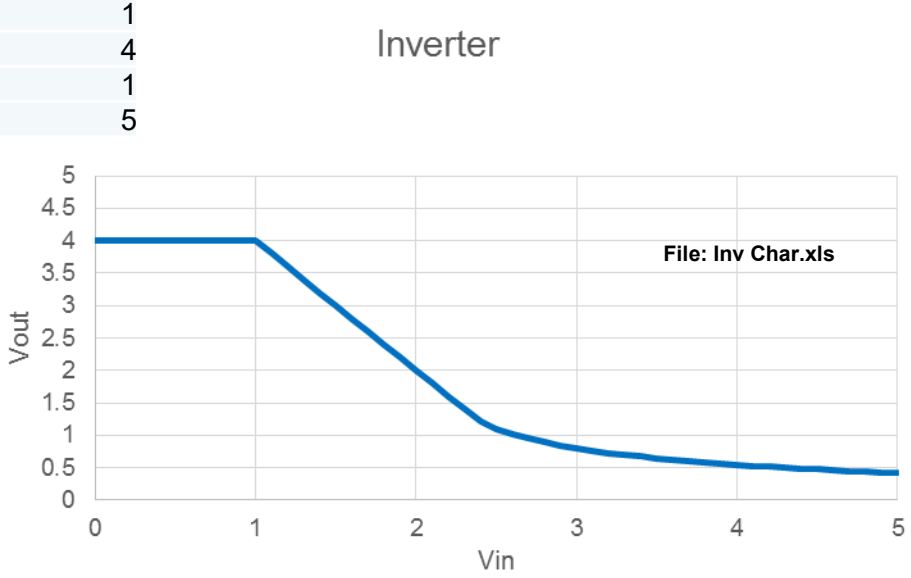


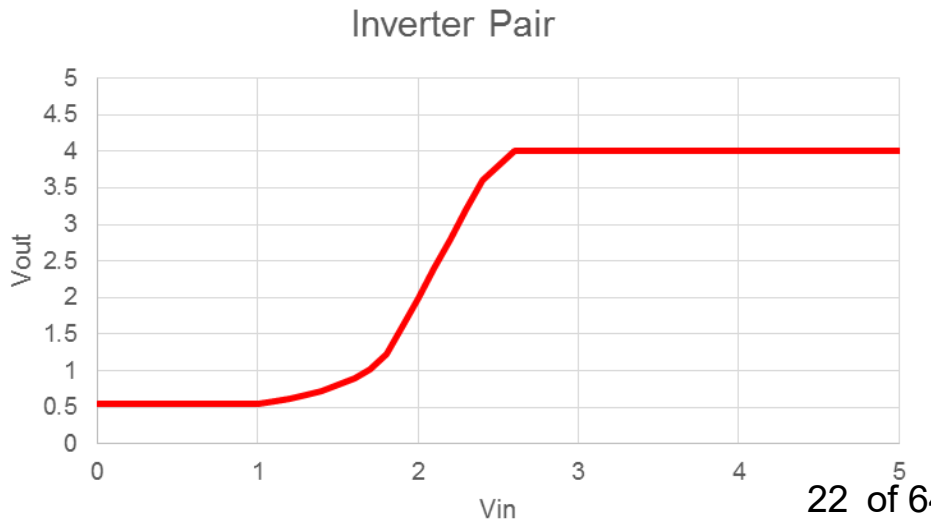
NMOS example



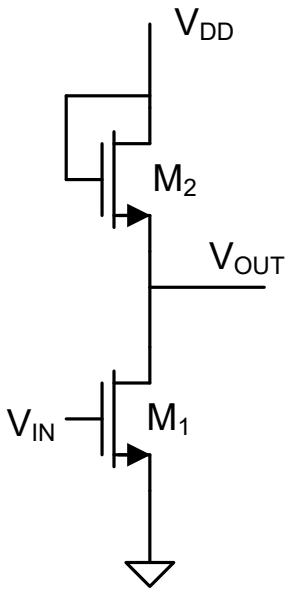
Enhancement
Load NMOS

VTH	1
W1/L1	4
W2/L2	1
VDD	5



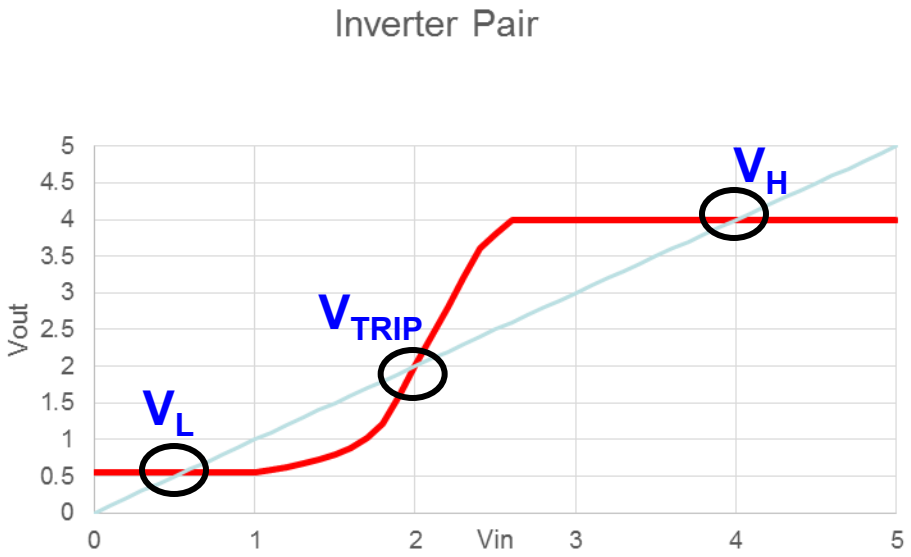


NMOS example



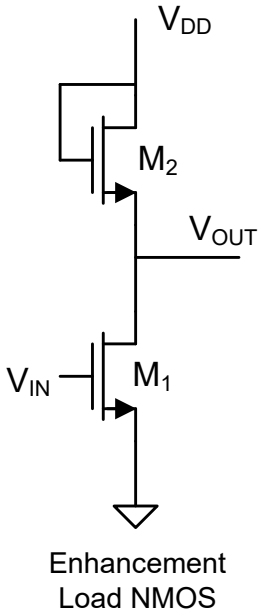
Enhancement
Load NMOS

VTH	1
W1/L1	4
W2/L2	1
VDD	5

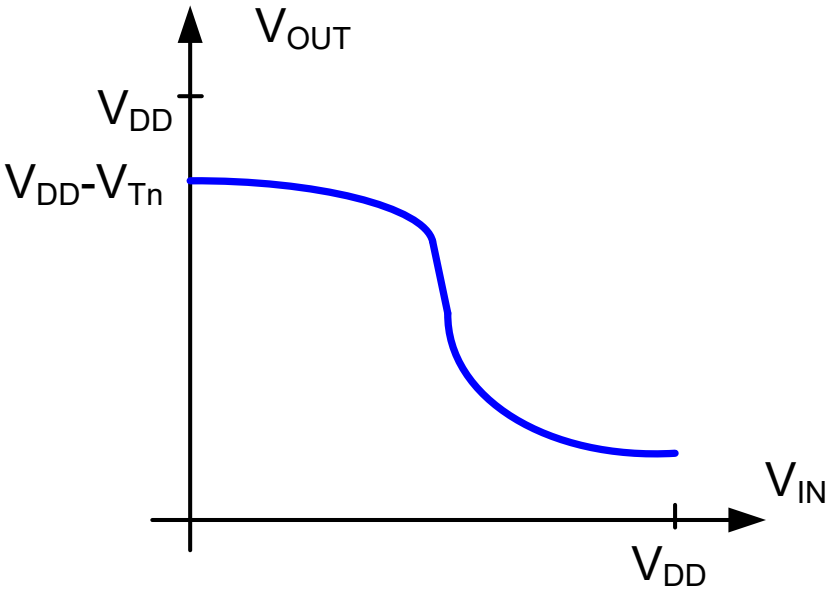


V_H=4V
V_L=0.55V
V_{TRIP}=2V

Other CMOS/MOS Logic Families

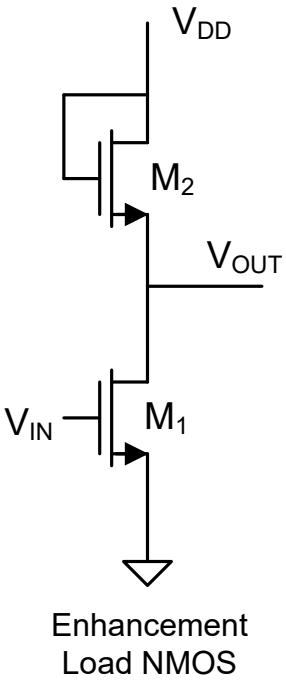


Enhancement
Load NMOS

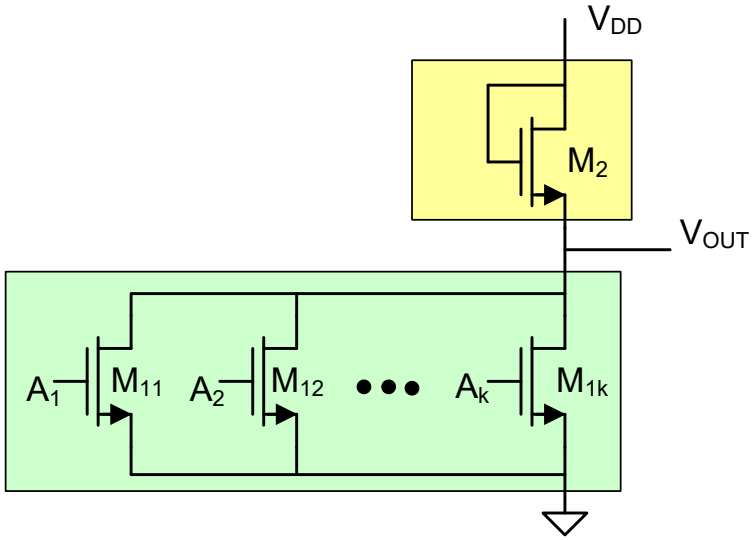


- **High and low swings are reduced**
- **Response time is slow on LH output transitions**
- **Static Power Dissipation Large when V_{OUT} is low (will sl**
- **Very economical process**
- **Termed "ratio logic" (because logic values dependent on device W/L ratios – USE UP DOF!)**
- **May not work for some device sizes**
- **Compact layout (no wells !)**
- **Can use very low cost process**
- **Available to use in standard CMOS process**

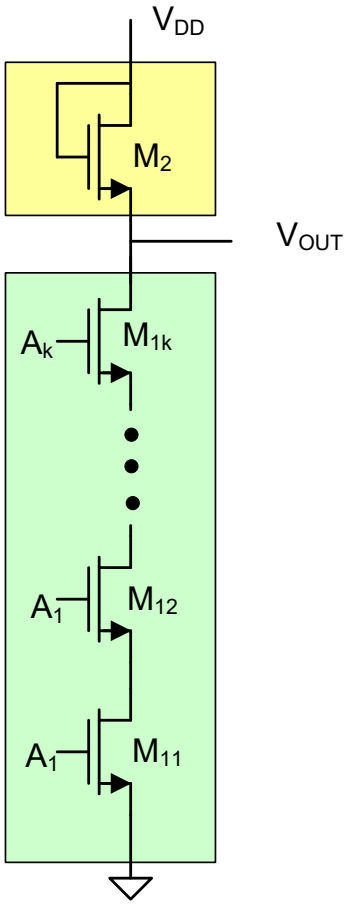
Other CMOS/MOS Logic Families



Enhancement Load NMOS



k-input NOR



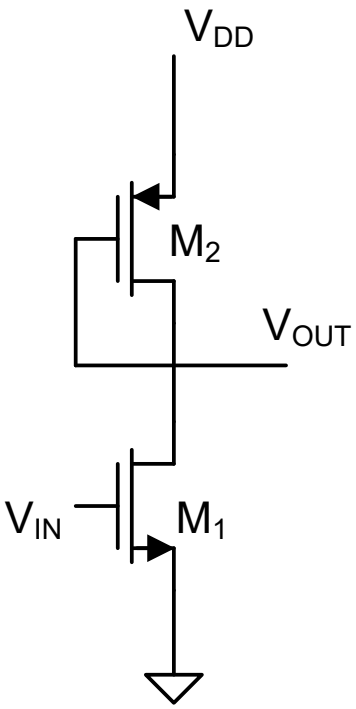
k-input NAND

- **Multiple-input gates require single transistor for each additional input**

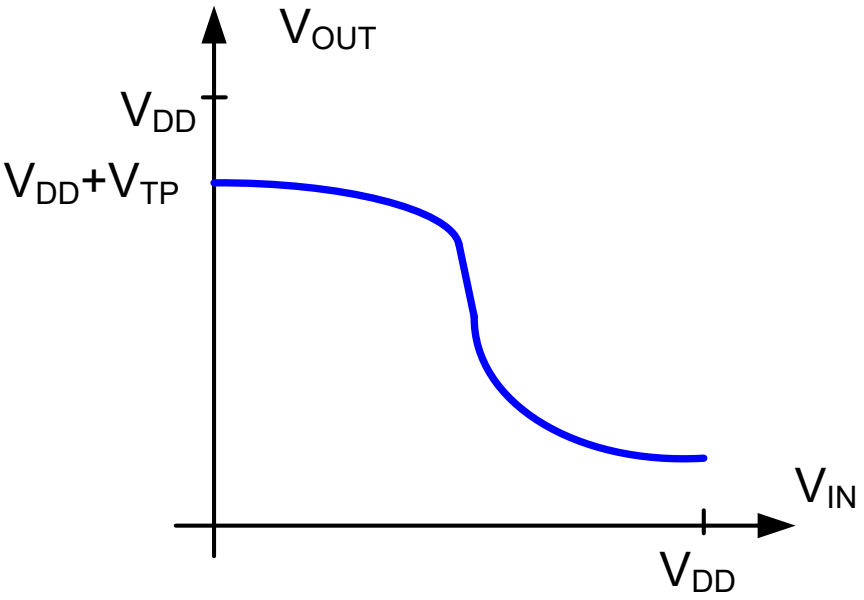
- **Still useful if many inputs are required**

(will be shown that static power does not increase with k)

Other CMOS/MOS Logic Families

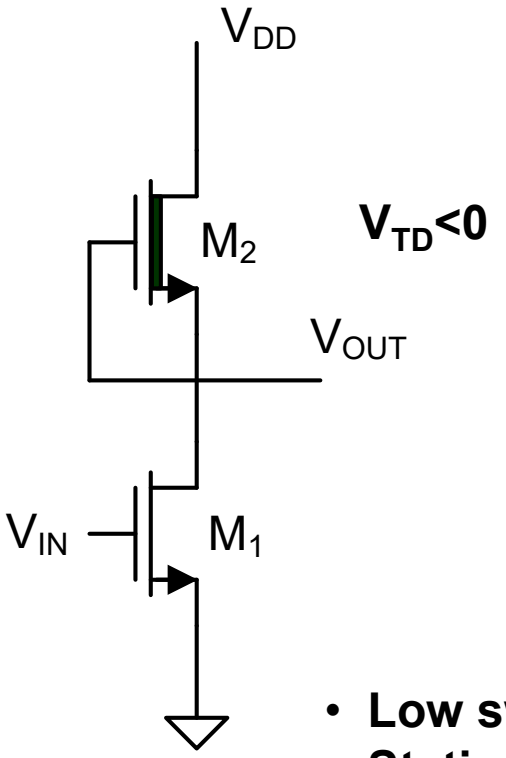


Enhancement Load
Pseudo-NMOS

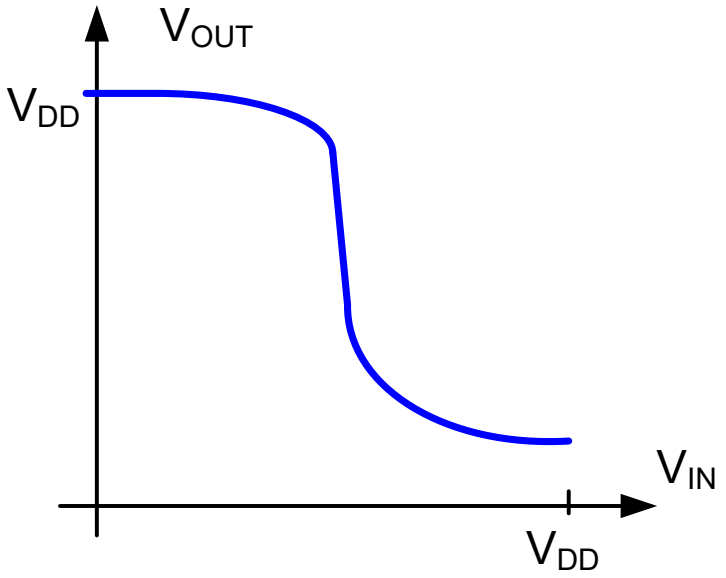


- **High and low swings are reduced**
- **Response time is slow on LH output transitions**
- **Static Power Dissipation Large when V_{OUT} is low**
- **Multiple-input gates require single transistor for each additional input**
- **Termed “ratio” logic**
- **Available to use in standard CMOS process**

Other CMOS/MOS Logic Families

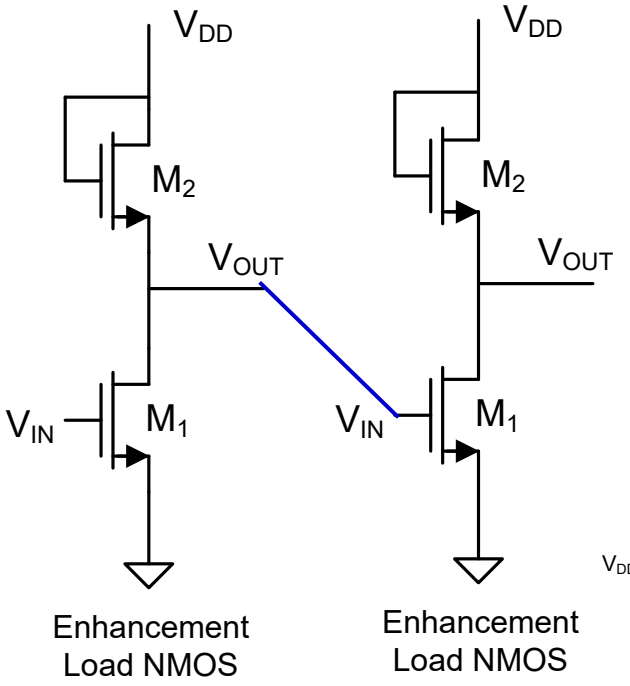


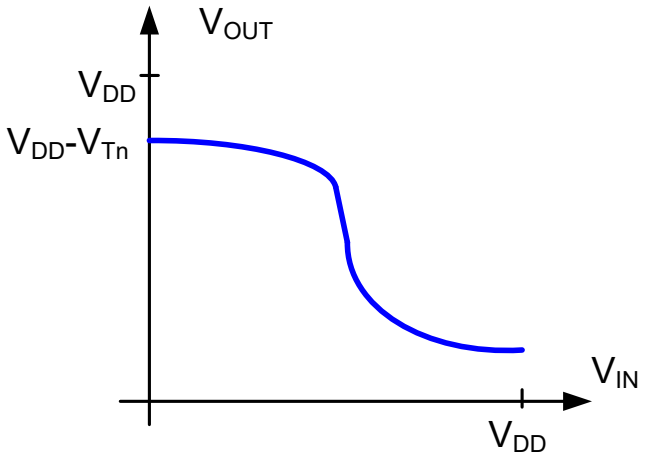
Depletion Load NMOS

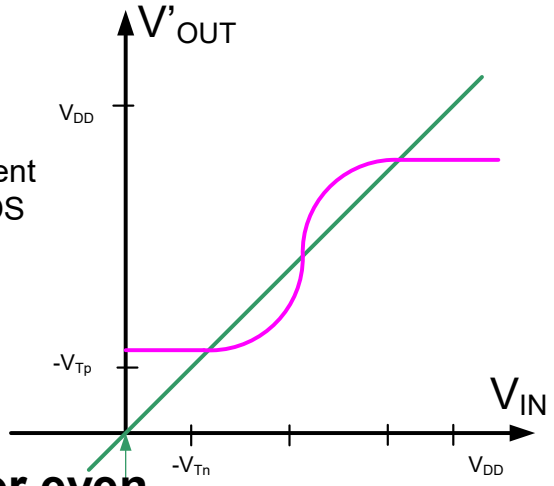


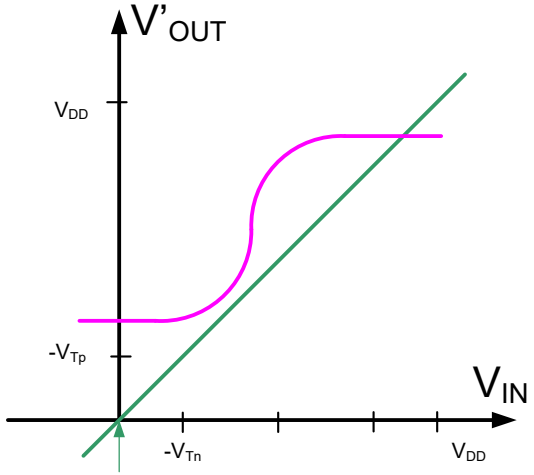
- **Low swing is degraded**
- **Static Power Dissipation Large when V_{OUT} is low**
- **Very economical process**
- **Better than Enhancement Load NMOS**
- **Termed "ratio" logic**
- **Compact layout (no wells !)**
- **Slow on L-H output transitions** (but not as slow as previous logic)
- **Dominant MOS logic until about 1985**
- **Depletion device not available in most processes today**

Other CMOS/MOS Logic Families



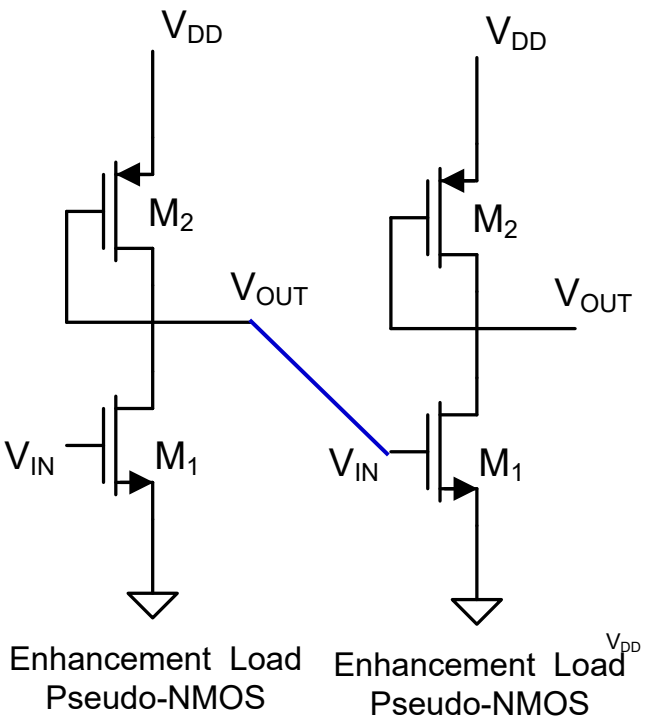


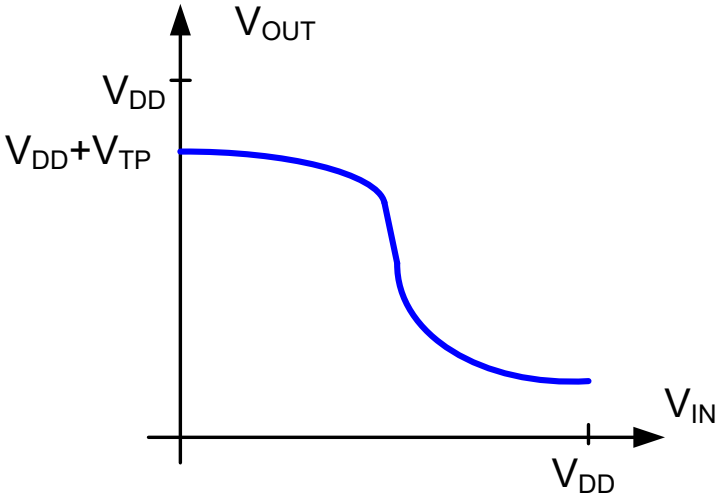


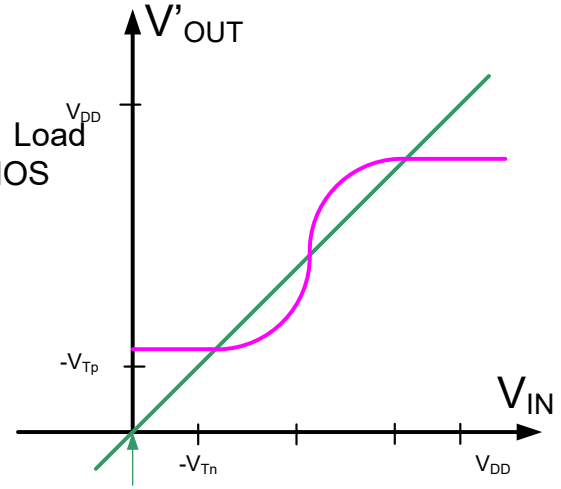


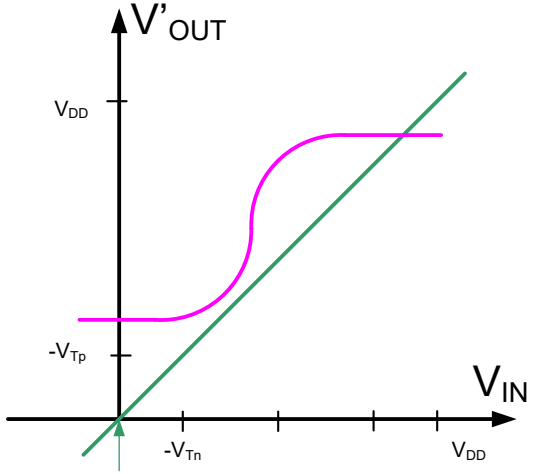
- **Reduced V_H-V_L**
- **Device sizing critical for even basic operation**
- **Shallow slope at V_{TRIP}**

Other CMOS/MOS Logic Families



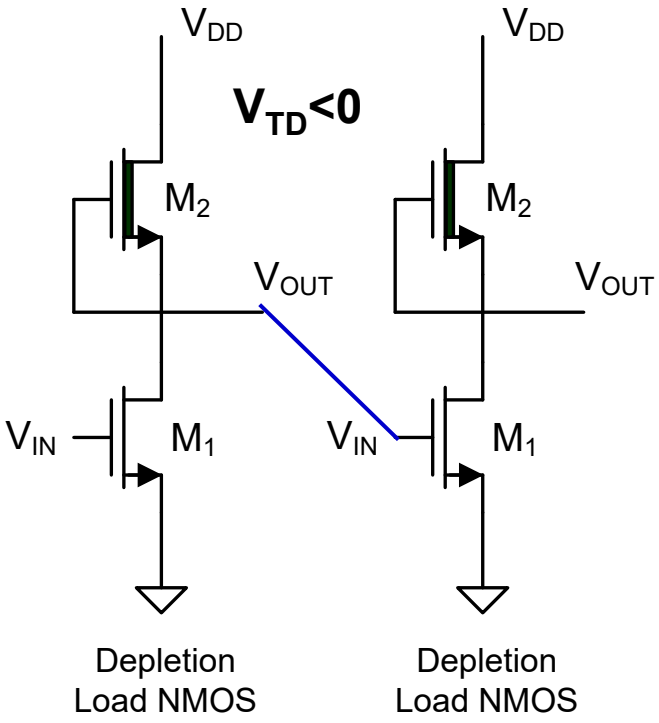


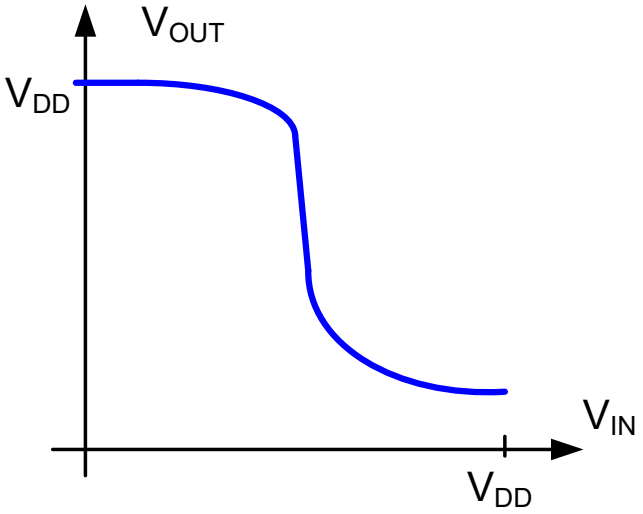


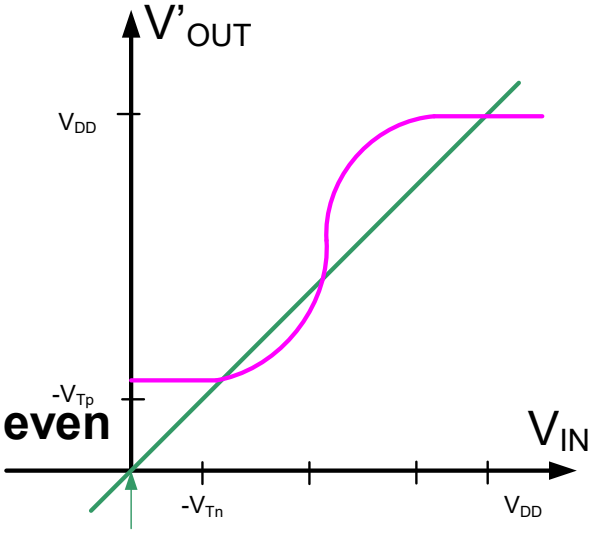


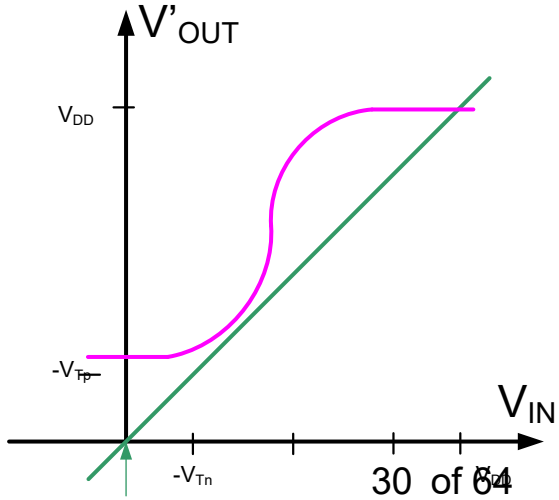
- **Reduced V_H-V_L**
- **Device sizing critical for even basic operation (DOF)**
- **Shallow slope at V_{TRIP}**

Other CMOS/MOS Logic Families









- **Reduced V_H-V_L**
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Digital Circuit Design

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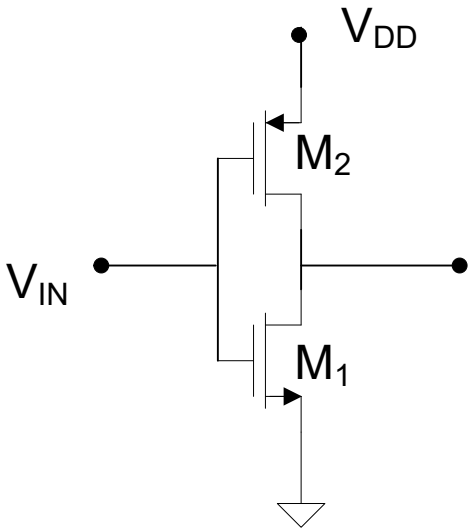
done

partial

Static Power Dissipation in Static CMOS Family

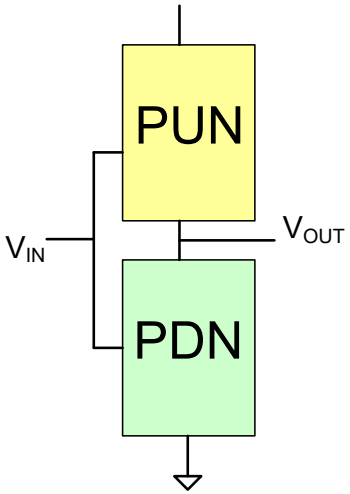


When V_{IN} is Low and V_{OUT} is High, M_1 is off and I_{D1}=0

When V_{IN} is High and V_{OUT} is Low, M_2 is off and I_{D2}=0

Thus, P_{STATIC}=0

This is a key property of the static CMOS Logic Family ➔the major reason Static CMOS Logic is so dominant

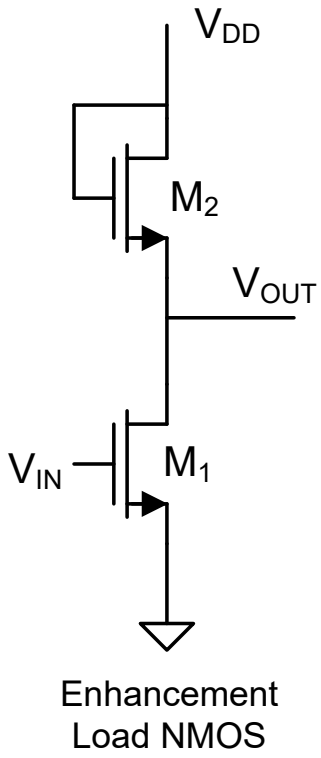


It can be shown that this zero static power dissipation property can be preserved if the PUN is comprised of p-channel devices, the PDN is comprised of n-channel devices and they are never both driven into the conducting states at the same time

Compound Gate in CMOS Process

Static Power Dissipation in Ratio Logic Families

Example:



Enhancement Load NMOS

Assume V_{DD}=5V
V_{Tn}=1V, μC_{OX} =10^{-4}A/V^2, W_1/L_1=1 and M_2 sized so that V_L is close to V_{Tn}

Observe:

$V_H=V_{DD}-V_{Tn}$

If $V_{IN}=V_H$, $V_{OUT}=V_L$ so

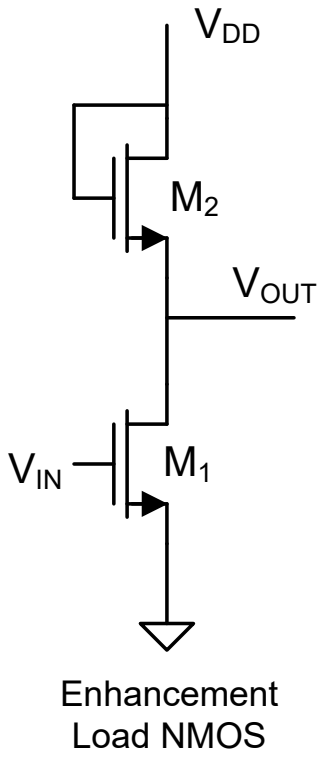
$$I_{D1}=\frac{\mu C_{OX} W_1}{L_1}\left(V_{GS1}-V_{Tn}-\frac{V_{DS1}}{2}\right)V_{DS1}$$

$$I_{D1}=10^{-4}\left(5-1-1-\frac{1}{2}\right)\bullet 1=0.25\text{mA}$$

P_L=(5V)(0.25mA)=1.25mW

Static Power Dissipation in Ratio Logic Families

Example:



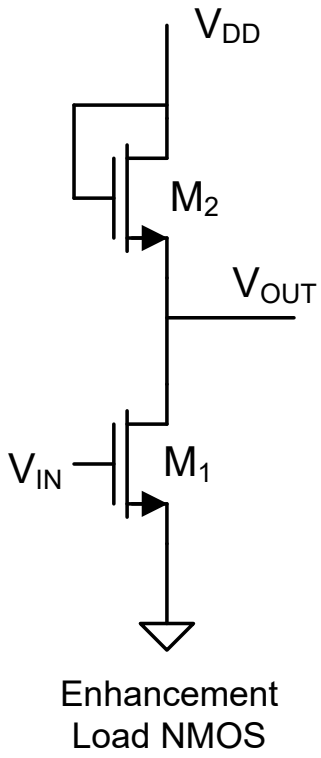
Assume V_{DD}=5V
V_T=1V, μC_{OX} =10^{-4}A/V^2, W_1/L_1=1 and M_2 sized so that V_L is close to V_{Tn}

P_L=(5V)(0.25mA)=1.25mW

If a circuit has 100,000 gates and half of them are in the V_{OUT}=V_L state, the static power dissipation will be

Static Power Dissipation in Ratio Logic Families

Example:



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P_L=(5V)(0.25mA)=1.25mW

If a circuit has 100,000 gates and half of them are in the V_{OUT}=V_L state, the static power dissipation will be

$$P_{STATIC} = \frac{1}{2}10^5 \bullet 1.25mW = \mathbf{62.5W}$$

This power dissipation is way too high and would be even larger in circuits with 100 million or more gates – the level of integration common in SoC circuits today

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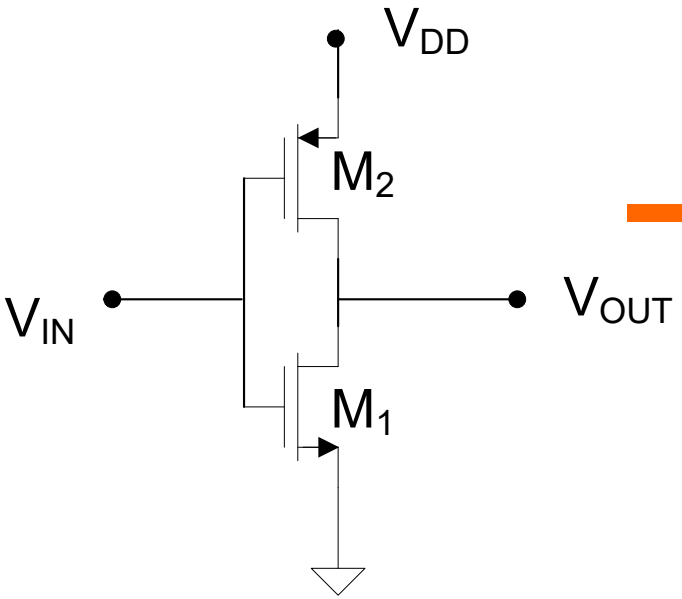
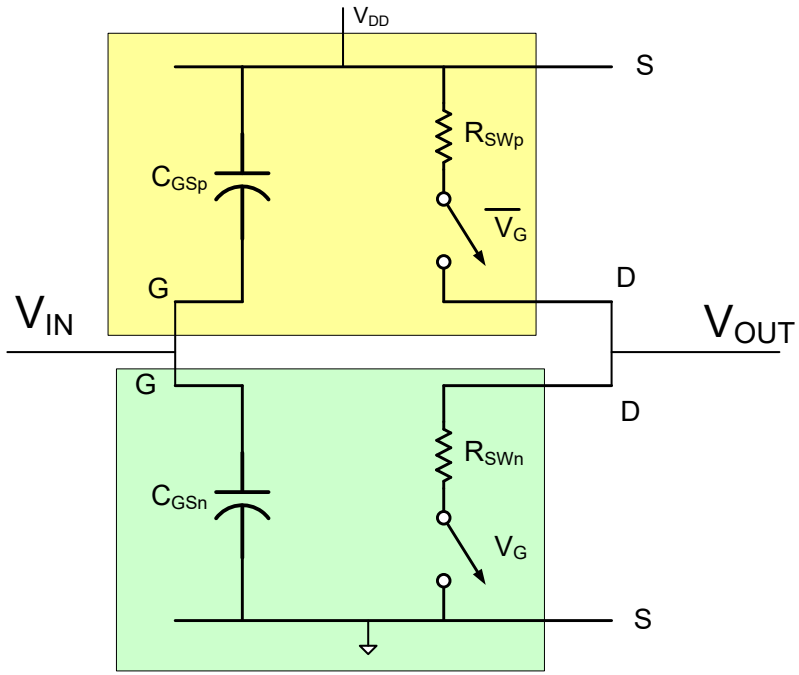
done

partial

Propagation Delay in Static CMOS Family

(Review from earlier discussions)

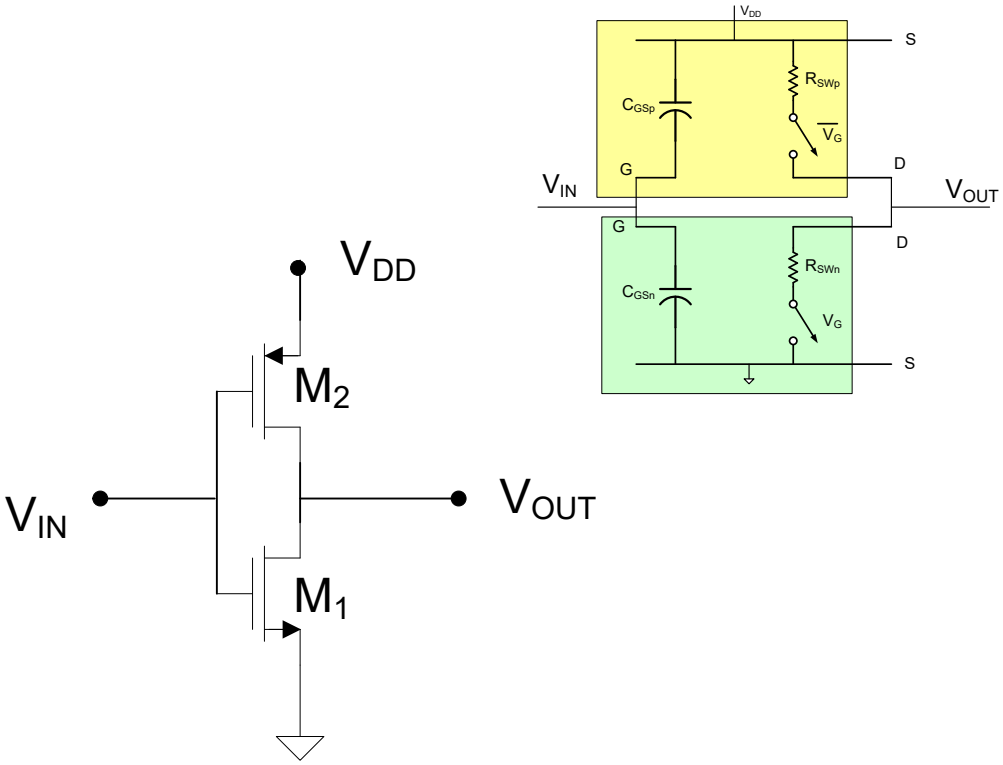


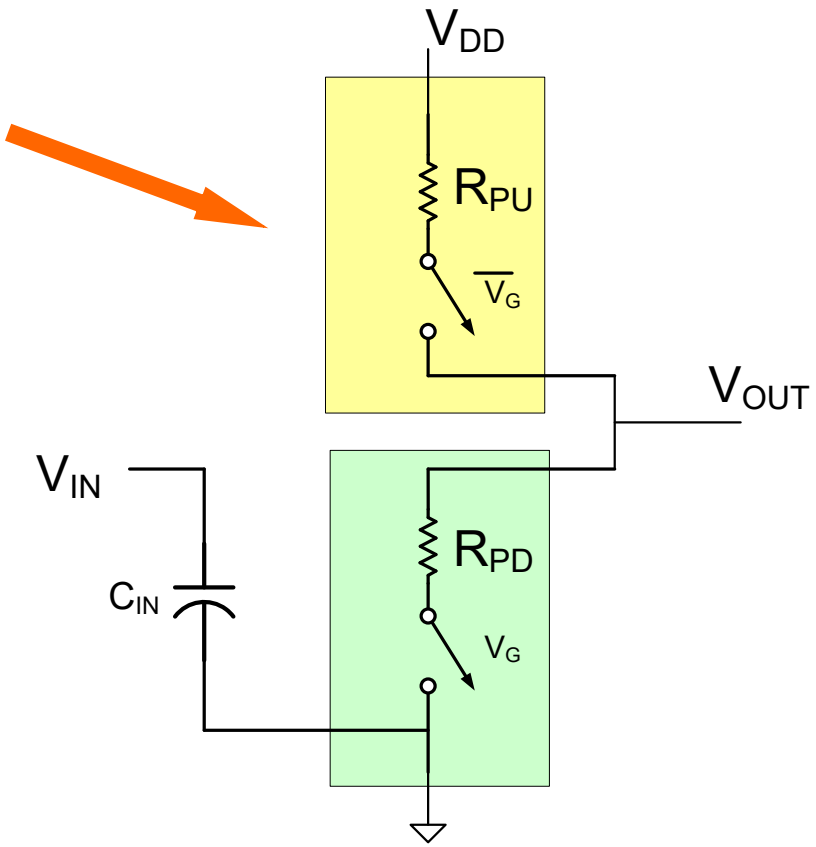


Switch-level model of Static CMOS inverter (neglecting diffusion parasitics)

Propagation Delay in Static CMOS Family

(Review from earlier discussions)





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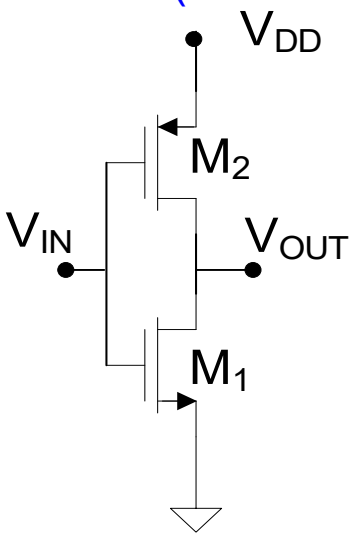
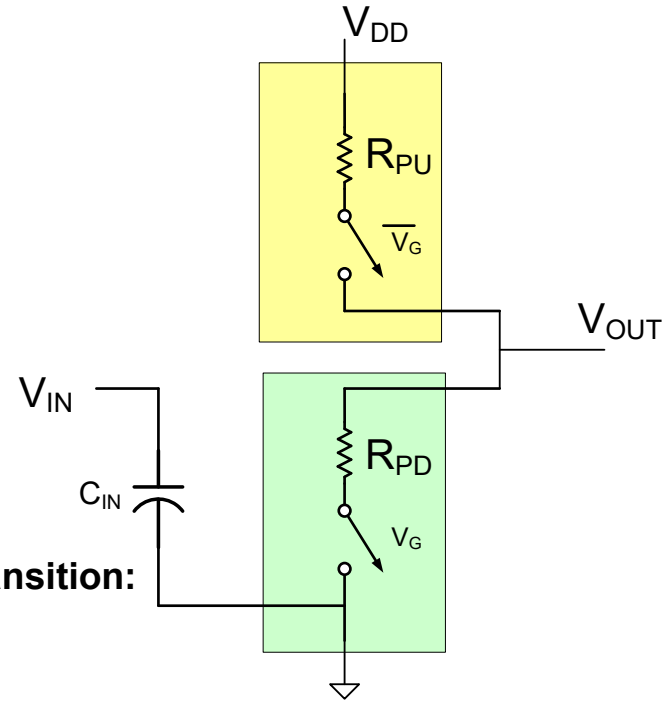




Since conducting transistor operating in triode through most of transition:

$$I_D \cong \frac{\mu C_{OX} W}{L}\left(V_{GS} - V_T - \frac{V_{DS}}{2}\right)V_{DS} \cong \frac{\mu C_{OX} W}{L}(V_{GS} - V_T)V_{DS}$$

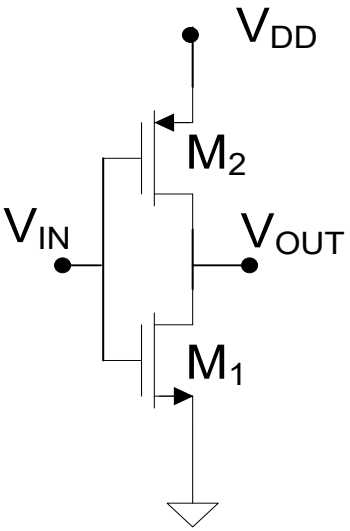
$$R_{PD} = \frac{V_{DS}}{I_D} = \frac{L_1}{\mu_n C_{OX} W_1 (V_{DD} - V_{Tn})}$$

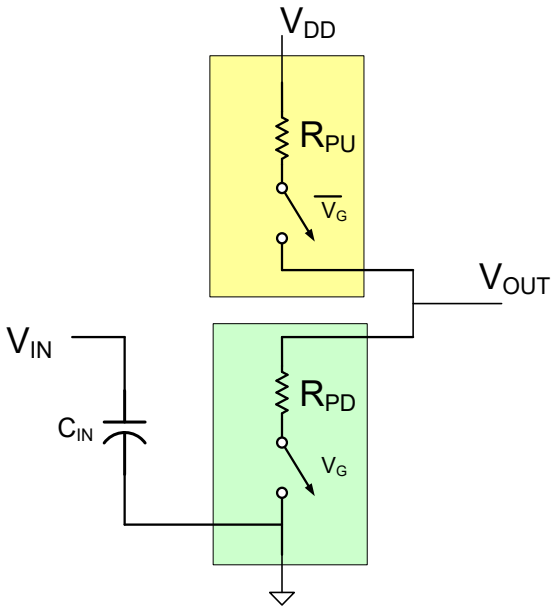
$$R_{PU} = \frac{V_{DS}}{I_D} = \frac{L_2}{\mu_p C_{OX} W_2 (V_{DD} + V_{Tp})}$$

$$C_{IN} = C_{OX}(W_1 L_1 + W_2 L_2)$$

Propagation Delay in Static CMOS Family

(Review from earlier discussions)





$$R_{PD} = \frac{L_1}{\mu_n C_{OX} W_1 (V_{DD} - V_{Tn})}$$

$$R_{PU} = \frac{L_2}{\mu_p C_{OX} W_2 (V_{DD} + V_{Tp})}$$

$$C_{IN} = C_{OX}(W_1 L_1 + W_2 L_2)$$

Example: Minimum-sized M_1 and M_2

If $u_n C_{OX}$=100μAV^{-2}, C_{OX}=4 fFμ^{-2} , $V_{Tn}=V_{DD}/5$, $V_{TP}=-V_{DD}/5$, $\mu_n/\mu_p=3$, $L_1=W_1=L_{MIN}$, $L_2=W_2=L_{MIN}$, L_{MIN}=0.5μ and V_{DD}=5V

(Note: This C_{OX} is somewhat larger than that in the 0.5u ON process)

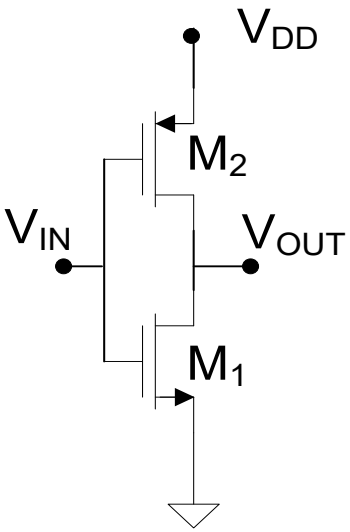
$$R_{PD} = \frac{1}{10^{-4} \bullet 0.8V_{DD}} = 2.5K\Omega$$

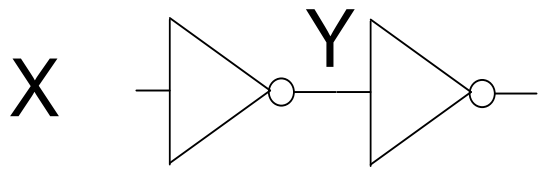
$$C_{IN} = 4 \bullet 10^{-15} \bullet 2L_{MIN}^2 = 2fF$$

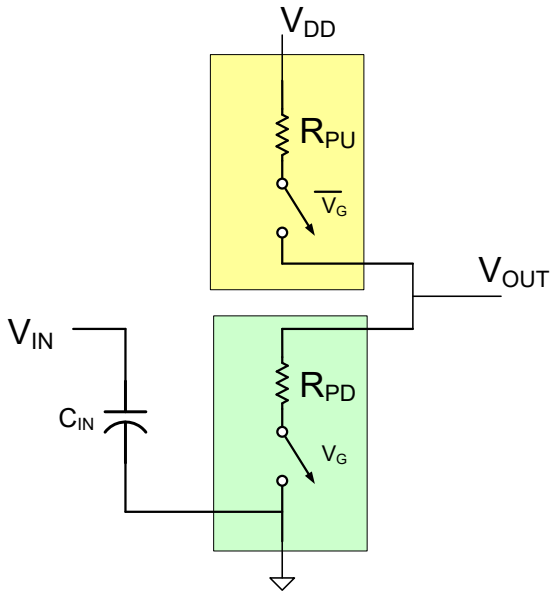
$$R_{PU} = \frac{1}{10^{-4} \bullet \frac{1}{3} \bullet 0.8V_{DD}} = 7.5K\Omega$$

Propagation Delay in Static CMOS Family

(Review from earlier discussions)







In typical process with Minimum-sized M_1 and M_2 :

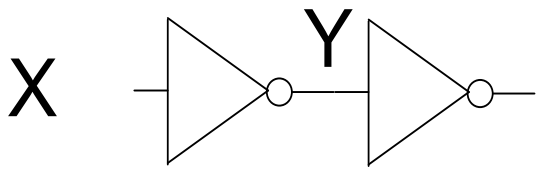
$$R_{PD} \cong 2.5K\Omega$$

$$R_{PU} \cong 3R_{PD} = 7.5K\Omega$$

$$C_{IN} \cong 2fF$$

Propagation Delay in Static CMOS Family

(Review from earlier discussions)



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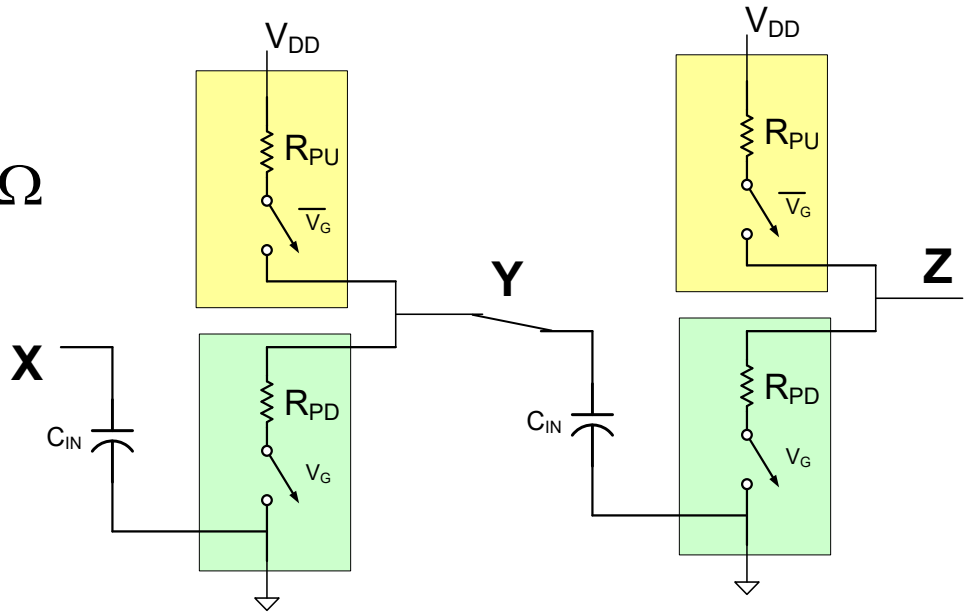
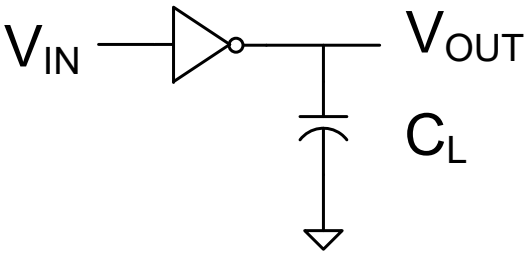


How long does it take for a signal to propagate from x to y?

Propagation Delay in Static CMOS Family

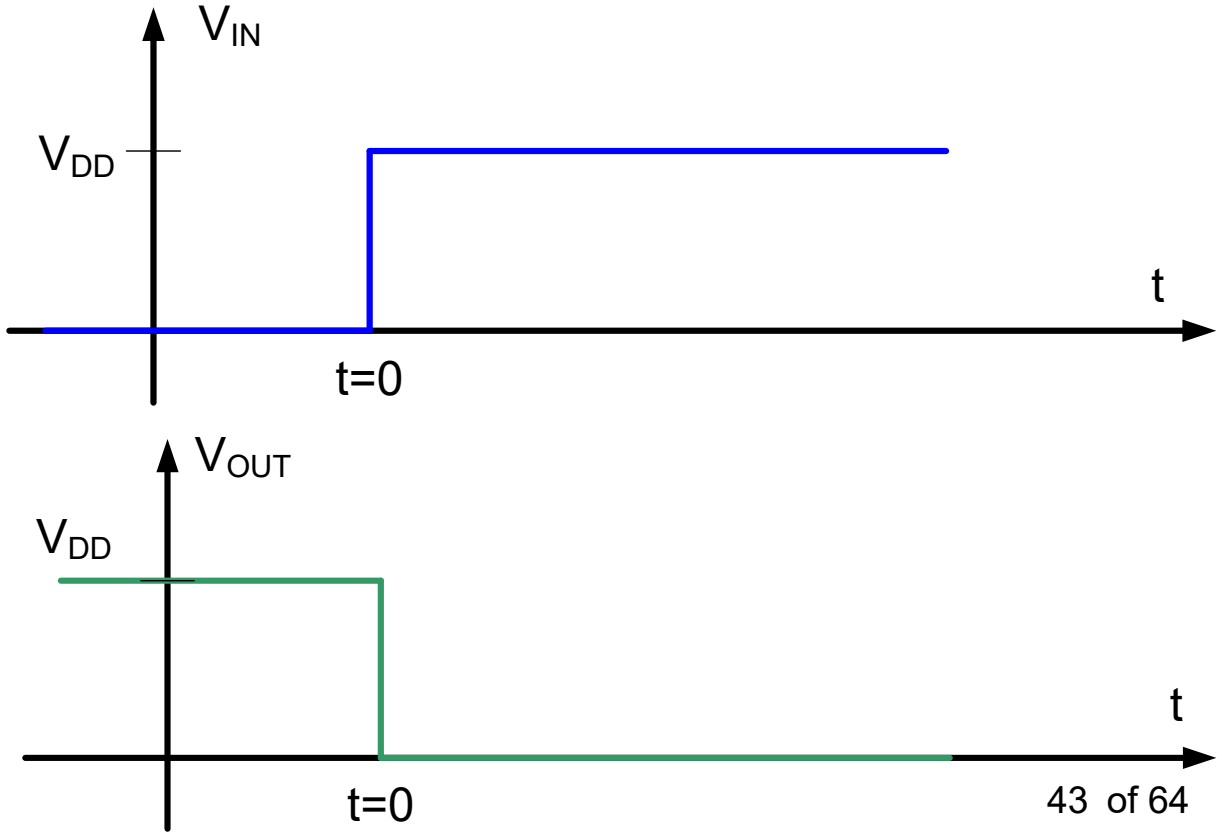
(Review from earlier discussions)

Consider:



For HL output transition, C_L charged to V_{DD}

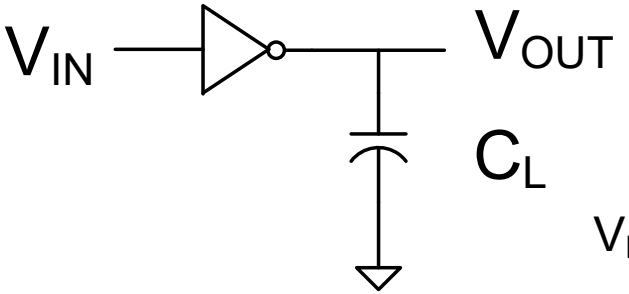
Ideally:



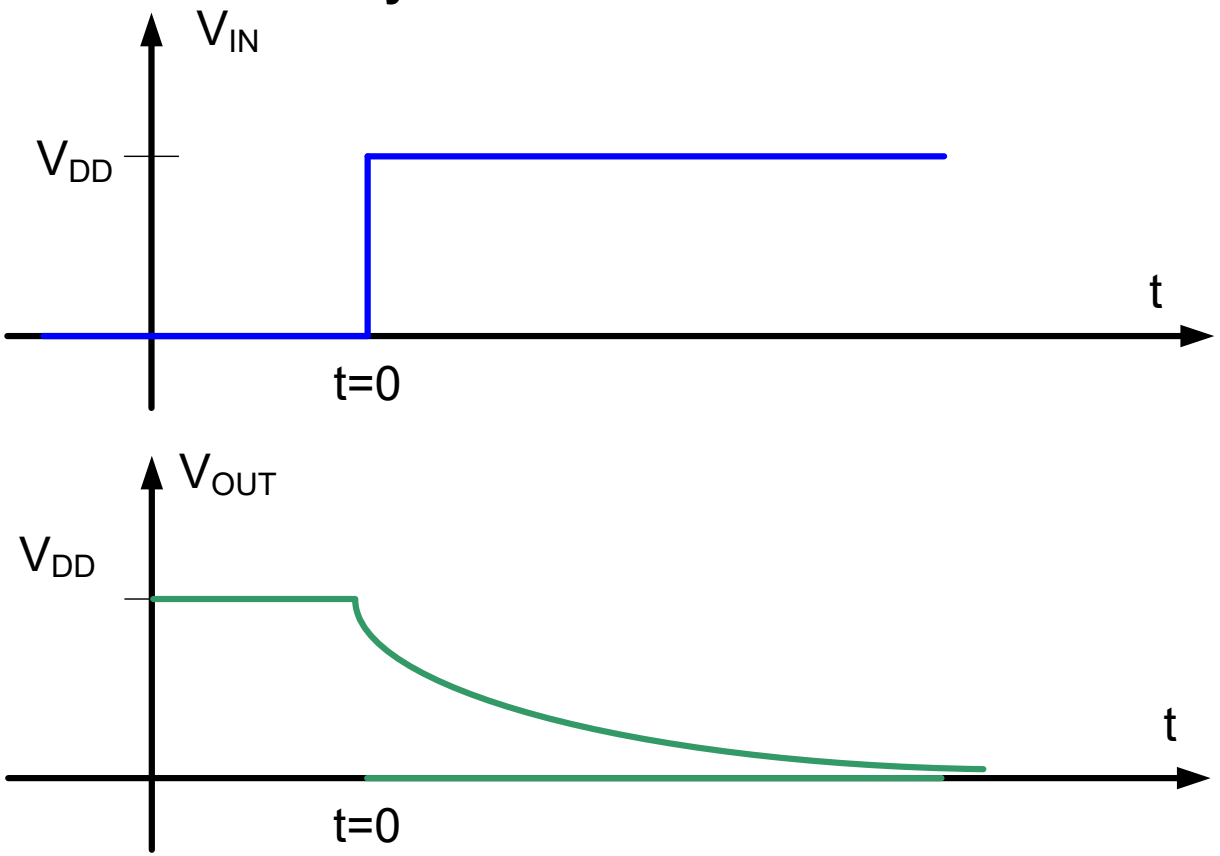
Propagation Delay in Static CMOS Family

(Review from earlier discussions)

For HL output transition, C_L charged to V_{DD}



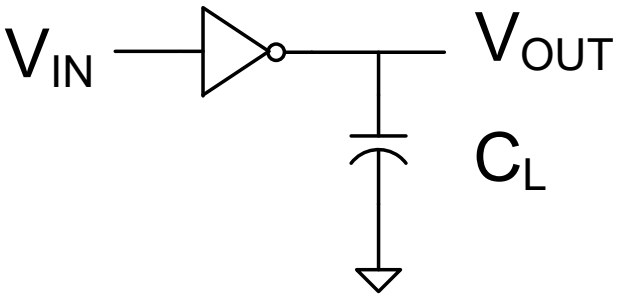
Actually:

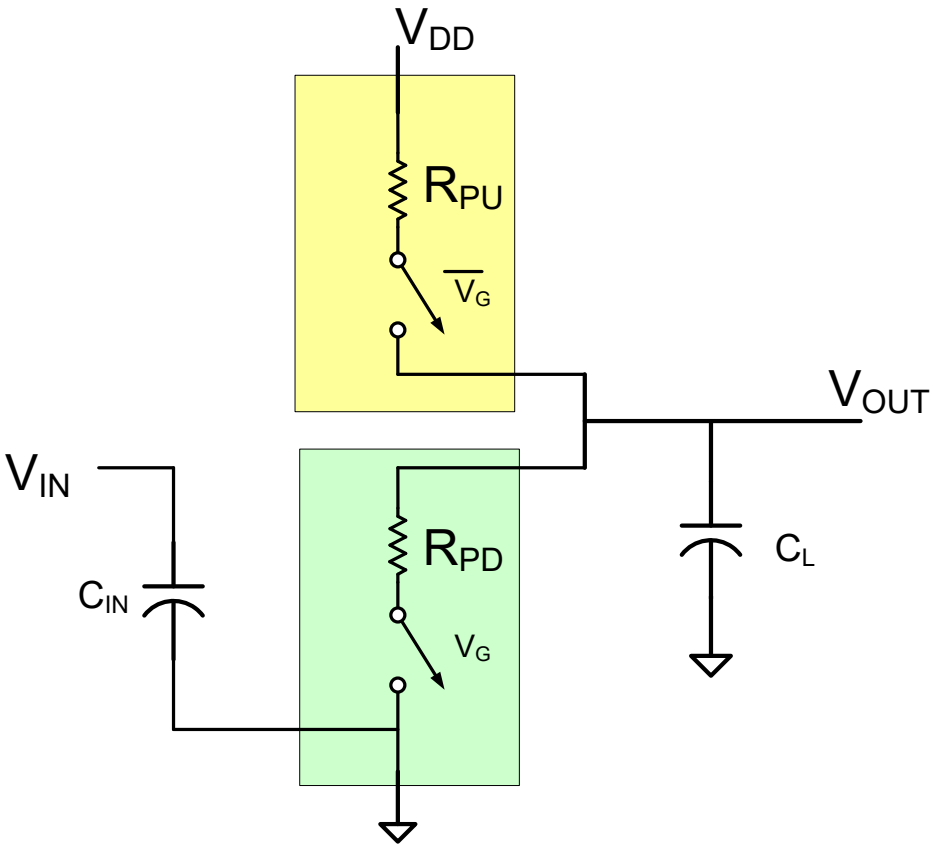


What is the transition time t_{HL} ?

Propagation Delay in Static CMOS Family

(Review from earlier discussions)

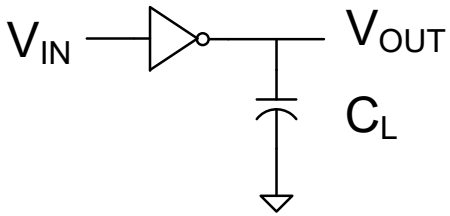


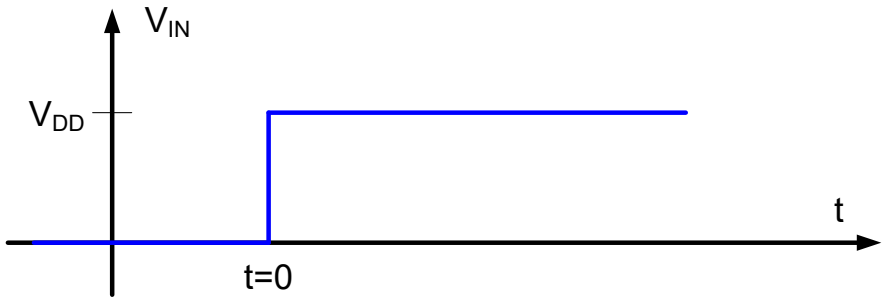


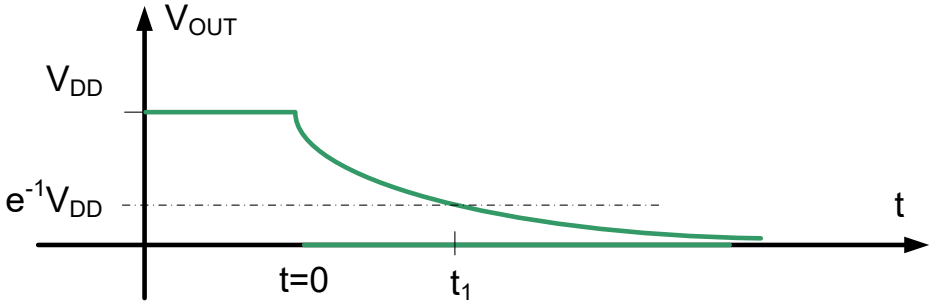
Propagation Delay in Static CMOS Family

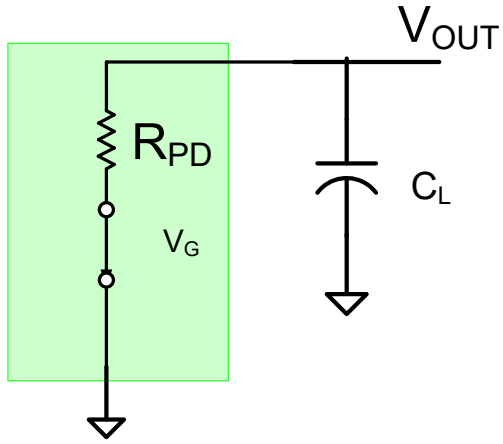
(Review from earlier discussions)

For HL output transition, C_L charged to V_{DD}









$$V_{OUT}(t) = F + (I - F)e^{\frac{-t}{\tau}} = 0 + (V_{DD} - 0)e^{-\frac{t}{R_{PD}C_L}}$$

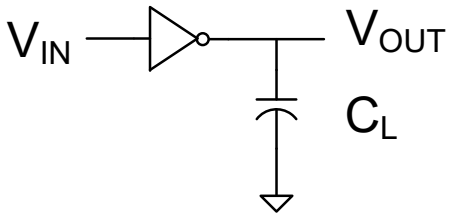
$$\frac{V_{DD}}{e} = V_{DD}e^{-\frac{t_1}{R_{PD}C_L}} \quad \Rightarrow \quad t_1 = R_{PD}C_L$$

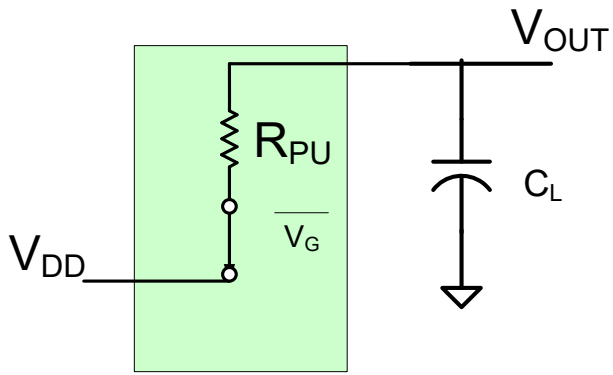
If V_{TRIP} is close to $V_{DD}/2$, t_{HL} is close to t_1

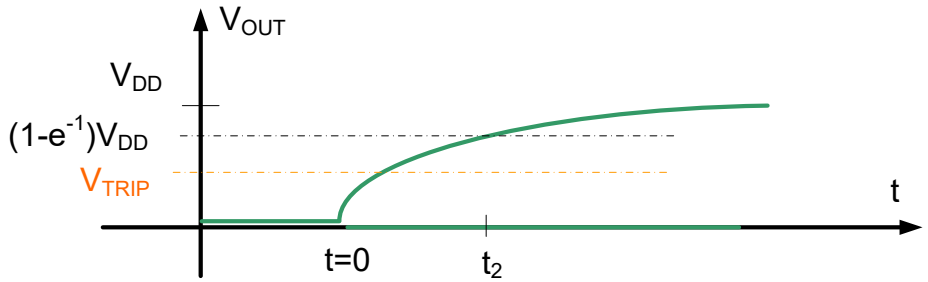
Propagation Delay in Static CMOS Family

(Review from earlier discussions)

For HL output transition, C_L charged to V_{DD}







$$t_{LH} \cong t_2 = R_{PU}C_L$$

Summary:

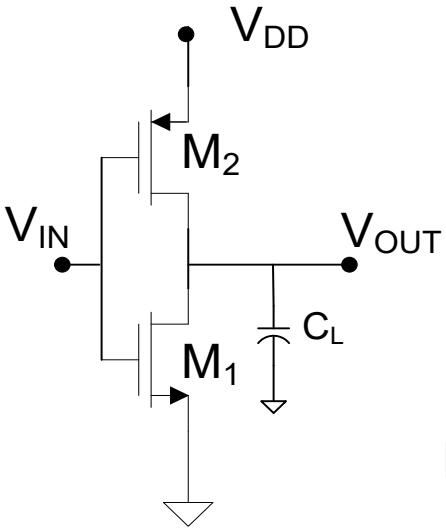
$$t_{LH} \cong R_{PU}C_L$$

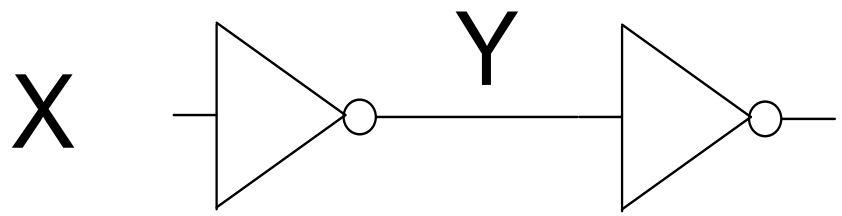
$$t_{HL} \cong R_{PD}C_L$$

For V_{TRIP} close to $V_{DD}/2$

Propagation Delay in Static CMOS Family

(Review from earlier discussions)





In typical process with Minimum-sized M_1 and M_2 :

$$t_{HL} \cong R_{PD}C_L \cong 2.5K \bullet 2fF = 5ps$$

$$t_{LH} \cong R_{PU}C_L \cong 7.5K \bullet 2fF = 15ps$$

(Note: This C_{ox} is somewhat larger than that in the 0.5u ON process)

Note: LH transition is much slower than HL transition

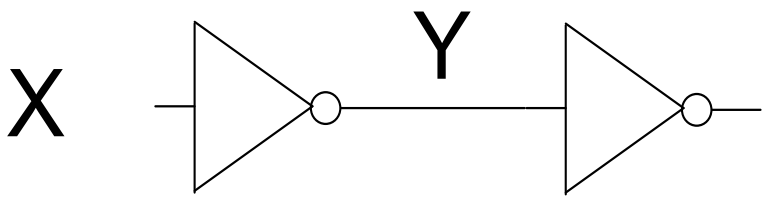
Propagation Delay in Static CMOS Family

Defn: The Propagation Delay of a gate is defined to be the sum of t_{HL} and t_{LH}, that is, $t_{PROP}=t_{HL}+t_{LH}$

$$t_{PROP} = t_{HL} + t_{LH} \cong C_L \left(R_{PU} + R_{PD}\right)$$

Propagation delay represents a fundamental limit on the speed a gate can be clocked at

For basic two-inverter cascade with minimum-sized devices in static 0.5um CMOS logic driving an identical device



$$t_{PROP} = t_{HL} + t_{LH} \cong 20p\,\text{sec}$$

Propagation Delay in Static CMOS Family for Arbitrarily Sized Devices

$$t_{PROP} = t_{HL} + t_{LH} \cong C_L (R_{PU} + R_{PD})$$

$$R_{PD} = \frac{L_1}{\mu_n C_{OX} W_1 (V_{DD} - V_{Tn})} \qquad R_{PU} = \frac{L_2}{\mu_p C_{OX} W_2 (V_{DD} + V_{Tp})} \qquad C_{IN} = C_{OX} (W_1 L_1 + W_2 L_2)$$

If $V_{Tn} = -V_{Tp} = V_T$ and if $C_L = C_{IN}$

$$t_{PROP} = C_{OX} (W_1 L_1 + W_2 L_2) \left(\frac{L_1}{\mu_n C_{OX} W_1 (V_{DD} - V_T)} + \frac{L_2}{\mu_p C_{OX} W_2 (V_{DD} - V_T)} \right)$$

If $L_2 = L_1 = L_{min}$, $\mu_n = 3\mu_p$,

$$t_{PROP} = \frac{L_{min}^2}{\mu_n (V_{DD} - V_T)} (W_1 + W_2) \left(\frac{1}{W_1} + \frac{3}{W_2} \right) = \frac{L_{min}^2}{\mu_n (V_{DD} - V_T)} \left(4 + \frac{W_2}{W_1} + 3\frac{W_1}{W_2}\right)$$

Note speed is a function of device sizing !

Can device sizing be used to minimize t_{PROP} ?

Propagation Delay in Static CMOS Family for Arbitrarily Sized Devices

For $L_2 = L_1 = L_{min}$, $\mu_n = 3\mu_p$,

$$t_{PROP} = \frac{L_{min}^2}{\mu_n (V_{DD} - V_T)} \left(4 + \frac{W_2}{W_1} + 3\frac{W_1}{W_2}\right)$$

Can device sizing be used to minimize t_{PROP} ?

Assume $W_1 = W_{MIN}$

$$\frac{\partial t_{PROP}}{\partial W_2} = \left[\frac{L_{min}^2}{\mu_n (V_{DD} - V_{TH})}\right]\left[\frac{1}{W_{MIN}} - 3\frac{W_{MIN}}{W_2^2}\right] = 0$$

$$\frac{1}{W_{MIN}} - 3\frac{W_{MIN}}{W_2^2} = 0$$

$$W_2 = \sqrt{3} W_{MIN}$$

$$t_{PROP} = \frac{L_{min}^2}{\mu_n (V_{DD} - V_T)} (4 + 2\sqrt{3}) \cong \frac{L_{min}^2}{\mu_n (V_{DD} - V_T)} (7.5)$$

Propagation Delay in Static CMOS Family for Arbitrarily Sized Devices

$$t_{PROP} = t_{HL} + t_{LH} \cong C_L \left(R_{PU} + R_{PD} \right)$$

If $V_{Tn}=-V_{Tp}=V_T$ and $C_L=C_{IN}$

For min size observe:

$$t_{PROP}=C_{OX}(W_1L_1+W_2L_2)\left(\frac{L_1}{\mu_n C_{OX} W_1 (V_{DD}-V_T)}+\frac{L_2}{\mu_p C_{OX} W_2 (V_{DD}-V_T)}\right)$$

If $L_2=L_1=L_{min}$, $W_1=W_2=W_{min}$, $\mu_n = 3\mu_p$,

$$t_{PROP}=\frac{L_{min}^2}{\mu_n (V_{DD}-V_T)}(W_1+W_2)\left(\frac{1}{W_1}+\frac{3}{W_2}\right)=\frac{L_{min}^2}{\mu_n (V_{DD}-V_T)}(2W_{min})\left(\frac{1}{W_{min}}+\frac{3}{W_{min}}\right)$$

For min size:

$$W_2=W_1=W_{min}$$

$$t_{PROP}=\frac{8L_{min}^2}{\mu_n (V_{DD}-V_T)}$$

Propagation Delay in Static CMOS Family for Arbitrarily Sized Devices

$$t_{PROP} = t_{HL} + t_{LH} \cong C_L \left(R_{PU} + R_{PD} \right)$$

If $V_{Tn}=-V_{Tp}=V_T$ and $C_L=C_{IN}$

For equal rise/fall (with $W_1=W_{min}$):

$$t_{PROP}=C_{OX}(W_1L_1+W_2L_2)\left(\frac{L_1}{\mu_n C_{OX} W_1 (V_{DD}-V_T)}+\frac{L_2}{\mu_p C_{OX} W_2 (V_{DD}-V_T)}\right)$$

If $L_2=L_1=L_{min}$, $W_1=W_{min}$, $\mu_n = 3\mu_p$,

$$t_{PROP}=\frac{L_{min}^2}{\mu_n (V_{DD}-V_T)}(W_1+W_2)\left(\frac{1}{W_1}+\frac{3}{W_2}\right) \quad \Rightarrow \quad W_2=3W_1$$

For equal rise/fall:

$$W_2=3W_1$$

$$t_{PROP}=\frac{8L_{min}^2}{\mu_n (V_{DD}-V_T)}$$

Propagation Delay in Static CMOS Family for Arbitrarily Sized Devices

$$t_{PROP} = t_{HL} + t_{LH} \cong C_L \left(R_{PU} + R_{PD} \right)$$

If $V_{Tn}=-V_{Tp}=V_T$ and $C_L=C_{IN}$

For $V_{TRIP}=V_{DD}/2$ (with $W_1=W_{min}$):

$$t_{PROP}=C_{OX}(W_1L_1+W_2L_2)\left(\frac{L_1}{\mu_n C_{OX} W_1 (V_{DD}-V_T)}+\frac{L_2}{\mu_p C_{OX} W_2 (V_{DD}-V_T)}\right)$$

If $L_2=L_1=L_{min}$, $W_1=W_{min}$, $\mu_n = 3\mu_p$,

$$t_{PROP}=\frac{L_{min}^2}{\mu_n (V_{DD}-V_T)}(W_1+W_2)\left(\frac{1}{W_1}+\frac{3}{W_2}\right)$$

Recall: $V_{TRIP}=V_{DD}/2$ (with $W_1=W_{min}$):

$$W_2=3W_1$$

$$t_{PROP}=\frac{8L_{min}^2}{\mu_n (V_{DD}-V_T)}$$

Propagation Delay in Static CMOS Family

$$t_{PROP} = t_{HL} + t_{LH} \cong C_L \left(R_{PU} + R_{PD} \right)$$

Summary:

If $V_{Tn}=-V_{Tp}=V_T$ and $C_L=C_{IN}$ and $L_2 = L_1 = L_{min}$, $\mu_n = 3\mu_p$,

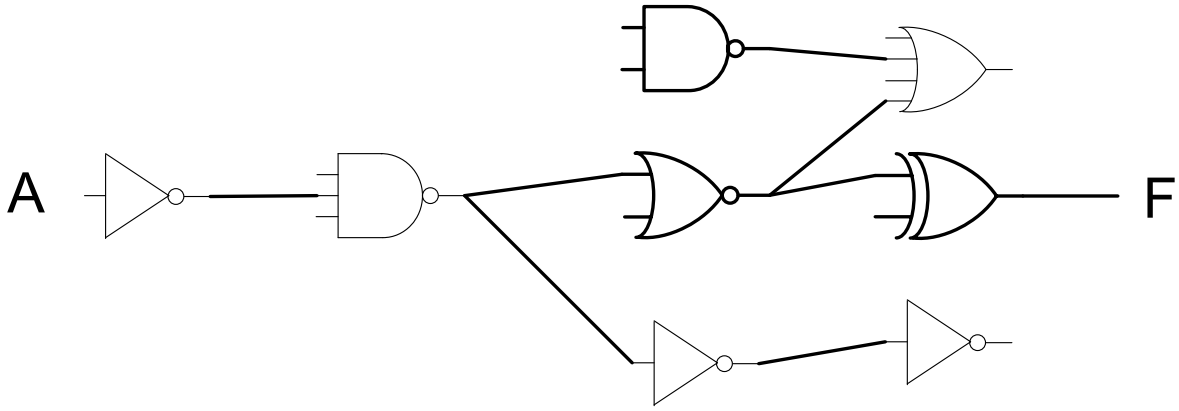
For min size:	For equal rise/fall:	For $V_{TRIP}=V_{DD}/2$:	For min delay:
$W_2=W_1=W_{min}$	$W_2=3W_1$	$W_2=3W_1$	$W_2=\sqrt{3}W_1$
$t_{PROP}=\frac{8L^2_{min}}{\mu_n(V_{DD}-V_T)}$	$t_{PROP}=\frac{8L^2_{min}}{\mu_n(V_{DD}-V_T)}$	$t_{PROP}=\frac{8L^2_{min}}{\mu_n(V_{DD}-V_T)}$	$t_{PROP}=\frac{(4+2\sqrt{3})L^2_{min}}{\mu_n(V_{DD}-V_T)}$

$\left(4+2\sqrt{3}\right) \cong 7.5$

- **Propagation Delay About the Same for 4 Sizing Strategies**
- **And for these sizing strategies all are near that of minimum delay !**
- **Have now introduced 4 device sizing strategies (3 based upon propagation delay and one to set $V_{TRIP}=V_{DD}/2$)**

Will return to the issue of device sizing later

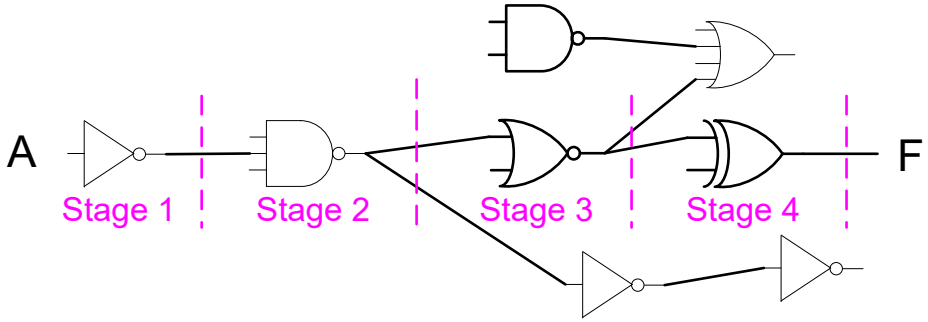
Propagation Delay in Static CMOS Family



The propagation delay through k levels of logic is approximately the sum of the individual propagation delays in the same path

Propagation Delay in Static CMOS Family

Example:



$$t_{HL}=t_{HL4}+t_{LH3}+t_{HL2}+t_{LH1}$$

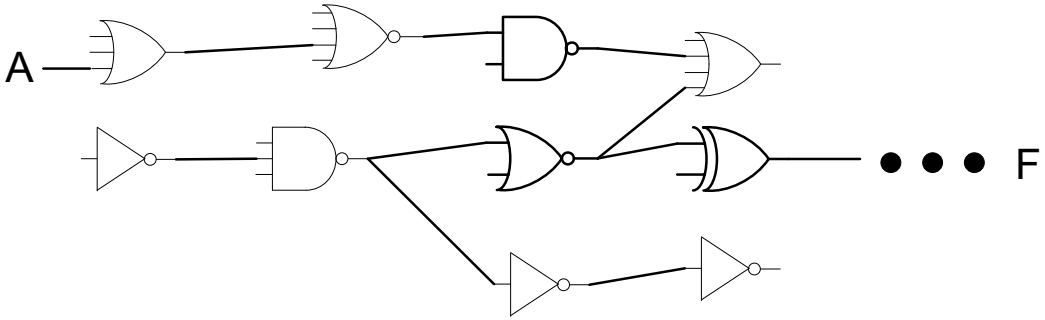
$$t_{LH}=t_{LH4}+t_{HL3}+t_{LH2}+t_{HL1}$$

$$t_{PROP}=t_{LH}+t_{HL}=(t_{LH4}+t_{HL3}+t_{LH2}+t_{HL1})+ (t_{HL4}+t_{LH3}+t_{HL2}+t_{LH1})$$

$$t_{PROP}=t_{LH}+t_{HL}=(t_{LH4}+t_{HL4})+(t_{LH3}+t_{HL3})+ (t_{LH2}+t_{HL2})+(t_{LH1}+t_{HL1})$$

$$t_{PROP}=t_{PROP4}+t_{PROP3}+t_{PROP2}+t_{PROP1}$$

Propagation Delay in Static CMOS Family



Propagation through k levels of logic

$$t_{HL} \cong t_{HLk} + t_{LH(k-1)} + t_{HL(k-2)} + \bullet\bullet\bullet + t_{XY1}$$

$$t_{LH} \cong t_{LHk} + t_{HL(k-1)} + t_{LH(k-2)} + \bullet\bullet\bullet + t_{YX1}$$

where X=H and Y=L if k odd and X=L and Y=h if k even

$$t_{PROP} = \sum_{i=1}^{k} t_{PROPk}$$

Will return to propagation delay after we discuss device sizing in more detail

Stay Safe and Stay Healthy !

End of Lecture 39